

AN ABSTRACT OF THE THESIS OF

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Title: A Switched-Current Bandpass Delta-Sigma Modulator

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Richard Schreier

Oversampled delta-sigma ($\Delta\Sigma$) data converters have become the method of choice for high-resolution conversion of low frequency signals. Such converters employ noise-shaping techniques and exhibit high linearity and reduced anti-aliasing filter complexity compared to Nyquist rate converters. Bandpass $\Delta\Sigma$ converters generalize the concept of noise-shaping to allow high-resolution conversion of high frequency narrowband signals. Such converters are well suited for use in AM radio receivers, cellular communication, spectrum analyzers and any special purpose instrumentation employing narrow band sources.

Switched-current (SI) circuit design is a relatively new technique for analog signal processing. In contrast to other signal processing techniques such as the switched-capacitor (SC) circuits which are traditionally used to implement $\Delta\Sigma$ modulators, SI circuits represent signals by currents rather than voltages. The principal advantage of SI circuits is that they are fully compatible with the standard digital CMOS VLSI technologies which are needed to implement the digital portion of a $\Delta\Sigma$ A/D.

This thesis applies the SI technique to the design of oversampled bandpass $\Delta\Sigma$ modulators. The intent of this work is to demonstrate that the SI technique is viable in this

context. To accomplish this a new SI architecture which implements pseudo N -path structures is required. The thesis develops a differential pseudo 2-path resonator capable of being clocked at 10 MHz to address this need. Not only does this new circuit demonstrate that SI techniques can be used to make bandpass $\Delta\Sigma$ converters, but the high speed operation of the circuit indicates that an SI implementation is better suited to high frequency operation than a more conventional SC implementation.

A Switched-Current Bandpass Delta-Sigma Modulator

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A Switched-Current Bandpass Delta-Sigma Modulator

Chapter 1. Introduction

This thesis examines the feasibility of using the switched-current technique to implement oversampled bandpass delta-sigma ($\Delta\Sigma$) analog-digital data converters. Such converters exhibit potential for performing high-resolution data conversion of narrowband high frequency signals. Existing switched-current topologies are investigated and new structures are developed for the implementation of such data converters.

1.1 Motivation

Signals in the real world are analog in nature. However, digital signals are more amenable to processing with integrated circuits than are analog signals. This necessitates transformation of the signal from an analog form to a digital form. This transformation is performed by an analog-to-digital (A/D) converter, which ideally converts a continuous-time analog signal into a digital signal containing all the information present in the original signal.

Oversampled delta-sigma ($\Delta\Sigma$) A/D converters have become the method of choice for high-resolution conversion of low frequency signals and so are ideally suited for use in audio applications. These converters employ noise-shaping techniques and exhibit high linearity, high tolerance to circuit imperfections and reduced anti-aliasing filter complexity compared to Nyquist rate converters.

The A/D conversion of high frequency signals, such as those encountered in video and radio applications, is quite demanding and until now could only be performed by

Nyquist-rate A/D converters. The advantages of the $\Delta\Sigma$ technique in such applications is the primary motivation for the development of bandpass $\Delta\Sigma$ data converters. Bandpass $\Delta\Sigma$ A/D converters retain many of the advantages of traditional $\Delta\Sigma$ converters, while providing the means to perform high-resolution conversion of narrow-band signals at high frequencies.

The most common approach to realizing $\Delta\Sigma$ modulators is with switched-capacitor (SC) circuits. While switched-capacitor modulators achieve high resolution, they require highly linear capacitors and so many mixed signal integrated circuits use a process with additional steps to make the linear capacitors. In a strictly digital integrated circuit these steps are not needed. Thus switched-capacitor circuits add expense to the process development and to the wafer costs of mixed-signal integrated circuits. Switched-current (SI) circuits provide an alternative to SC circuits. In contrast to SC circuits, SI circuits represent signals by currents rather than voltages. The principal advantage of switched-current circuits is that they do not require linear capacitors and hence the resulting circuits are fully compatible with standard digital CMOS VLSI technologies.

1.2 Outline of the Thesis

Chapter 2 provides the reader with the necessary background information on bandpass delta-sigma modulation. In addition, switched-current circuits are introduced and existing topologies and structures are explained in more detail. Chapter 3 describes the implementation of the modulator from a theoretical standpoint and Chapter 4 deals with more practical concerns involved in circuit design and layout. Chapter 5 concludes the thesis and gives directions for future work.

Chapter 2. Prior Art

This chapter reviews the state-of-the-art for bandpass delta-sigma converters and switched-current circuits.

2.1 Delta-Sigma in a Nutshell

Oversampling techniques are based on sampling the input signal at a rate much greater than the Nyquist rate, and have gained acceptance since they allow high-resolution conversion while providing high tolerance to circuit imperfections. The most popular approach to oversampling is delta-sigma ($\Delta\Sigma$) modulation, which by feeding back the quantized signal produces a greater reduction in quantization noise than would occur through oversampling alone. To understand how this is possible, consider the first-order oversampled $\Delta\Sigma$ A/D converter shown in Figure 2.1. The modulator consists of an analog integrator, a single-bit A/D converter, or quantizer, and a feedback path comprising a single-bit D/A converter. Such an analog feedback loop around a low-resolution quantizer has the ability to shape the spectrum of the quantization noise away from an arbitrary passband [1]. The high degree to which this is feasible has made delta-sigma the premier A/D technique for narrowband signals.

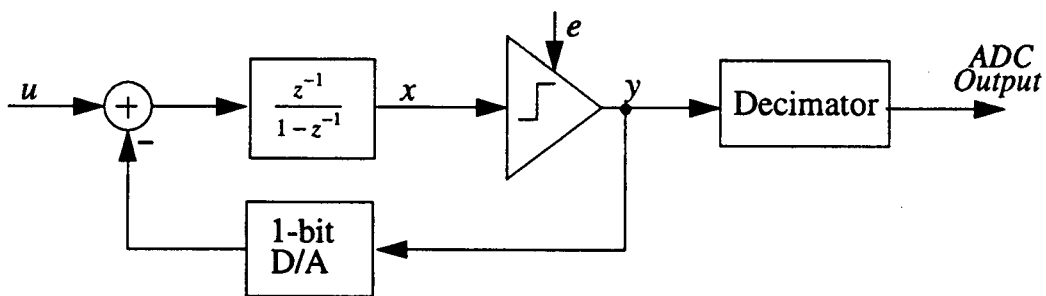


Figure 2.1: A first-order delta-sigma A/D converter.

Referring to Figure 2.1, the output of the modulator is given by

$$Y(z) = X(z) + E(z), \quad (2.1)$$

where

$$X(z) = \frac{z^{-1}}{(1 - z^{-1})} [U(z) - Y(z)]. \quad (2.2)$$

Multiplying Eq. (2.1) by $(1 - z^{-1})$ yields

$$(1 - z^{-1}) Y(z) = (1 - z^{-1}) X(z) + (1 - z^{-1}) E(z) \quad (2.3)$$

$$(1 - z^{-1}) Y(z) = z^{-1} [U(z) - Y(z)] + (1 - z^{-1}) E(z). \quad (2.4)$$

So that

$$Y(z) = z^{-1} U(z) + (1 - z^{-1}) E(z). \quad (2.5)$$

From the above relationship it is apparent that the output is just a delayed version of the input plus the quantization noise filtered by the noise transfer function $(1 - z^{-1})$. Thus the first-order modulator nulls the quantization noise at low frequencies and so preserves the low frequency content of the input u . Applying a digital lowpass filter to y removes the bulk of the quantization noise and yields a high-resolution digital representation of the input as shown in Figure 2.2. It is worthwhile to note that the use of single-bit quantization makes the modulator immune to differential nonlinearities. With a single-bit quantizer, the only possible errors are gain and offset errors. There is no differential nonlinearity. Delta-sigma modulation thus offers the means to make inherently linear analog-digital and digital-analog data converters.

This approach can be extended to higher order modulators. More specifically, the output of an L th-order $\Delta\Sigma$ modulator is

$$Y(z) = z^{-1}U(z) + \frac{(1 - z^{-1})^L E(z)}{D(z)}. \quad (2.6)$$

where $D(z)$ is chosen to ensure modulator stability. One of the problems faced in the use of $\Delta\Sigma$ modulators is that the clock frequency must be many times higher than the upper frequency of interest. That is the oversampling ratio must be large. For high frequency signals this is unpractical. The need for a high oversampling ratio can be alleviated by using higher-order modulators, making high-frequency operation feasible. Adopting a higher-order structure also suppresses the limit-cycle tones that are present in the first-order modulator.

2.2 Bandpass Delta-Sigma Data Converters

The previous section explained how quantization noise can be suppressed in a narrow band around DC by placing the noise transfer function zeros near $\omega = 0$. This concept of noise shaping can be extended to the bandpass case, wherein the noise transfer function zeros are placed at some other frequency, $\omega_0 \neq 0$ [5] [10]. The quantization noise is thereby suppressed in a narrow band of frequency centered at ω_0 so that the output signal is an accurate digital representation of the input signal in this narrow band. Figure 2.3

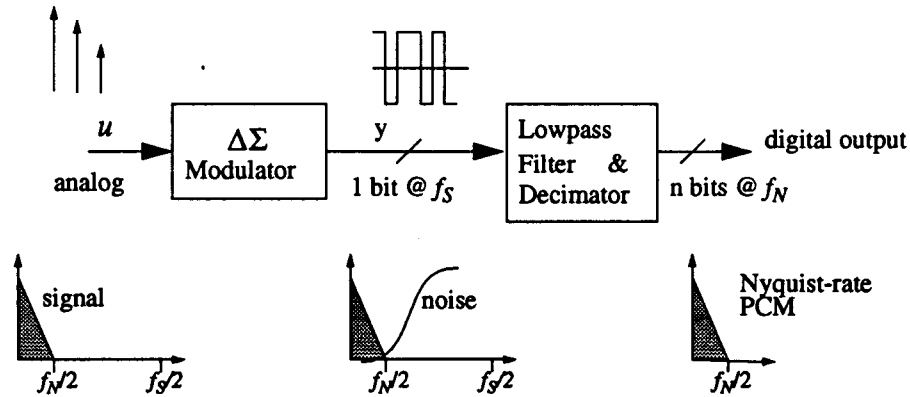


Figure 2.2.: A delta-sigma modulator based A/D converter.

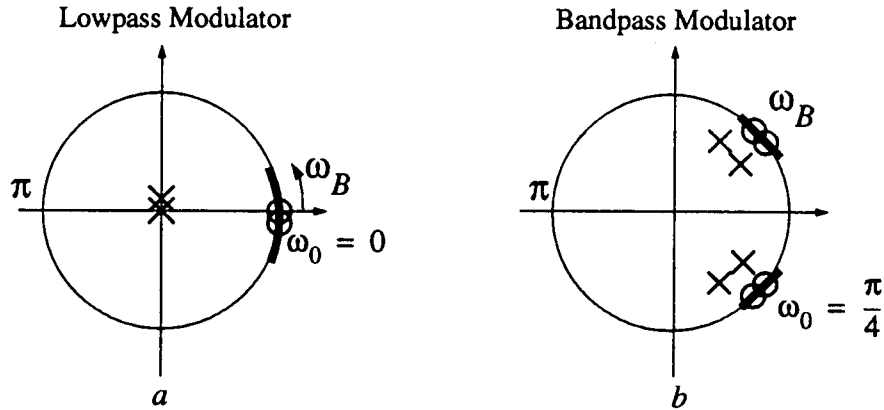


Figure 2.3: Comparison of pole and zero placements of error transfer functions for (a) a second-order lowpass modulator and (b) a fourth-order bandpass modulator.

illustrates the pole and zero placement of the noise transfer functions for lowpass and bandpass delta-sigma modulators. For narrow-band signals away from DC, the noise shaping of the bandpass $\Delta\Sigma$ modulator results in high signal to noise (SNR) at much lower sampling rates than would be required by a lowpass $\Delta\Sigma$ converter for the same signal, since a high oversampling ratio (OSR) can be achieved without a high ratio of sampling to center frequency. The OSR is defined as one half the sampling rate divided by the width of the band of interest. Thus a center frequency of $\pi/2$ with a bandwidth of π corresponds to an oversampling ratio of one. Bandpass $\Delta\Sigma$ A/D converters are well suited for use in the front-end of AM radio receivers, allowing direct conversion to digital at either intermediate or radio frequency. An early conversion to digital results in a more robust system and provides opportunities for dealing with the multitude of standards present in commercial AM stereo broadcasting. Other applications include cellular radio, spectrum analyzers and any special purpose instrumentation employing narrow band sources.

Current state of the art circuits include a fourth-order modulator by Jantzi et al. [6] for bandpass signals centered at 455 kHz with 10 kHz bandwidth, numbers quite typical of

AM broadcasting. The modulator is clocked at 1.82 MHz and realizes an SNR of 63 dB. The modulator was implemented by modifying a commercial digital-audio delta-sigma converter and is the first reported fully monolithic implementation of bandpass noise shaping. Another design by Tröster et al. [14], converts bandpass signals centered at 6.5 MHz with 200 kHz bandwidth. The modulator is implemented on a $1.2\mu\text{m}/7\text{ GHz}$ BiCMOS analog/digital array, and achieves an SNR of 55 dB. A more recent implementation by Longo et al. [7] achieves 15 bit dynamic range over a 30 kHz bandwidth centered at 1.8 MHz using a 7.2 MHz sampling frequency and operating on a single 5V supply.

Lowpass modulators are normally realized using the cascade-of-resonators structure, illustrated in Figure 2.4. The performance of the $\Delta\Sigma$ modulator depends heavily on the accuracy of the noise transfer function (NTF) zeros, which in turn are determined by the γ coefficients. In lowpass modulators, these coefficients are very close to zero and small percentage errors in the γ_i do not significantly affect the performance of the modulator.

In bandpass modulators, the γ coefficients are on the order of unity and small errors can produce significant effects. For the component errors to have only a marginal effect, the tolerance on the γ_i must be approximately $1/R$, where R is the oversampling ratio. For narrowband applications, R can be as large as 1000 and hence the component precision required to achieve accurate NTF zero placement can be excessive. In such cases, using an N -path structure is more practical.

However, N -path circuits have their own set of problems. Clock feedthrough can cause noise peaks in the center of the passband. Also mismatch between the paths can cause out-of-band quantization noise to mix into the signal band and degrade the SNR. These

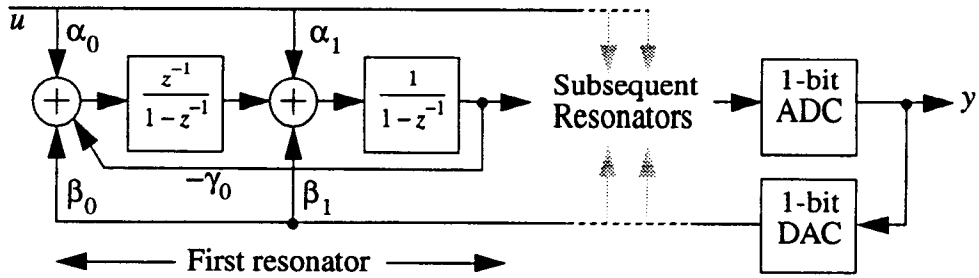


Figure 2.4: The cascade of resonators structure.

problems can be avoided by using a pseudo N -path structure [9] in which the paths share components in such a way as to ensure exact matching. N -path structures will be discussed in more detail in the next chapter.

2.3 Switched-Current Circuits

Single chip digital systems require analog circuits at their interface with the outside world and switched-capacitor (SC) circuits have been the traditional solution [12]. However switched-capacitors circuits have never been compatible with standard VLSI processing. Their need for linear floating capacitors has led to special process options being added to standard digital processes. In mixed-signal chips where the analog part sometimes occupies only 10 percent of the total chip area, the extra expense is difficult to justify. In order to overcome this problem, switched-current (SI) circuits have been developed [3]. These circuits use currents instead of charges to represent discrete-time analog signals and so do away with the need for linear capacitors. SI circuits also have potential for high speed operation and are smaller and simpler than their SC counterparts.

The basic switched-current cell is the current track and hold circuit, illustrated in Figure 2.5. This cell is just a simple current mirror with a MOS switch. When the switch is

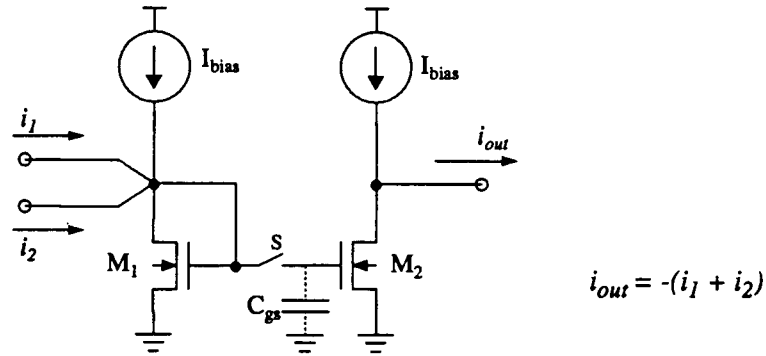


Figure 2.5: A current track and hold circuit.

closed the circuit acts as a simple current mirror. The gate-to-source capacitances of both transistors are charged to a voltage V_{gs} which causes both transistors to sink a current $I_{bias} + i_1 + i_2$. Consequently the output current is given by $i_{out} = -(i_1 + i_2)$. This is called the *track* mode. When the switch is opened, the output is isolated from the input. This is the *hold* mode. A voltage close to V_{gs} is held on the C_{gs} of transistor M2, and sustains a current close to $-(i_1 + i_2)$ at the output. The circuit shown above can therefore perform addition, inversion and delay [3]. Multiplication by a constant is also possible by suitably scaling the transistors, but it is not very accurate.

One of the biggest problems with this type of circuit is the precise matching required between the two transistors. Any mismatch due to process variations in either the dimensions or the threshold voltages of the two transistors can introduce errors in the output current. One way to get around this problem is to use a dynamic current copier [15] illustrated in Figure 2.6. This configuration uses only one transistor to first track and then hold the input current. Thus transistor matching is not required. On phase 1, the transistor is diode connected and conducts a current $I_{bias} + i_{in}$ and, as before, V_{gs} is stored on the C_{gs} of the transistor. On phase 2, the transistor maintains its current and $i_{out} = -i_{in}$.

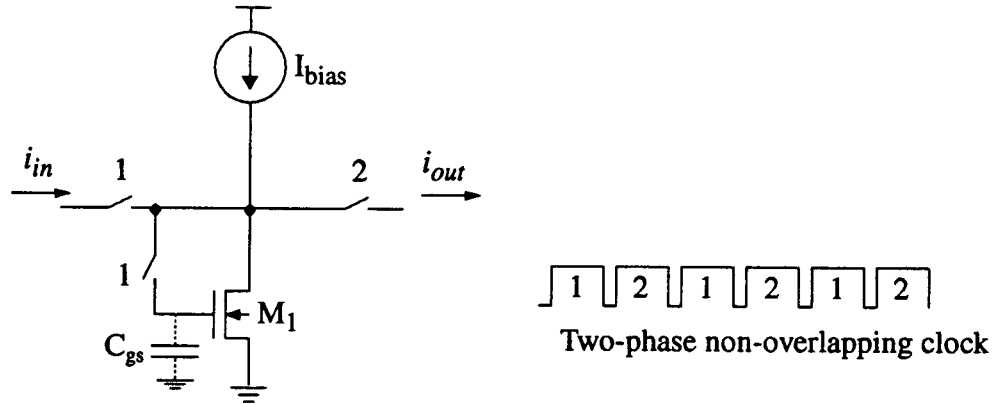


Figure 2.6: A dynamic current copier.

Both the track and hold circuit and the dynamic current copier circuit display a current memory property. This results from the voltage V_{gs} being stored on the C_{gs} of the transistor and this highlights a crucial distinction from SC circuits. SC circuits require linear floating capacitors to perform linear transfer of voltages. In contrast, a SI memory cell requires only a grounded capacitor, which need not be linear, to hold V_{gs} at the value imposed by the current $I_{bias} + i_{in}$.

To make switched-current circuits competitive with switched-capacitor circuits they must have both comparable accuracy and be equally amenable to design-automation techniques. Since the operations of addition, multiplication and delay are essentially the same for both, design automation is straightforward. However, the simple current copier cell, comprising only a transistor and a switch, produces unacceptably large errors. If the drain-to-source voltage of the transistor in phase 2 (imposed by the load) differs from that occurring on phase 1 then there will be an error in the output current due to the channel length modulation effect. The need to overcome this problem motivated the search for alternative structures.

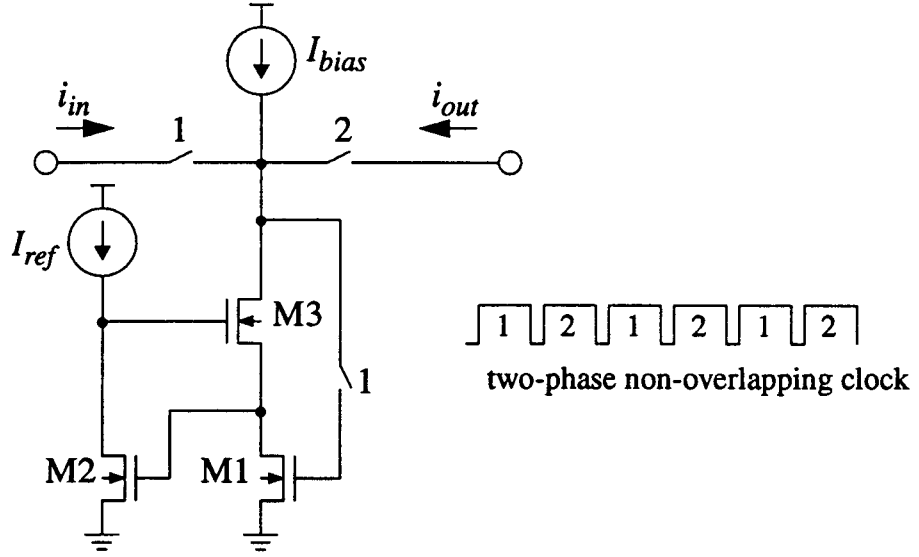


Figure 2.7: The regulated cascode current memory cell.

The structure chosen as the starting point for this work is the regulated cascode current memory cell [13], illustrated in Figure 2.7. The operation of this cell is quite similar to that of the dynamic current copier. On phase 1, transistor M_1 is in essence diode connected and its gate to source capacitance C_{gs1} charges until it can sustain a drain current equal to $(I_{bias} + i_{in})$. During phase 2, the voltage V_{gs1} is held on C_{gs1} and same amount of current is sustained in transistor M_1 . The advantage of this circuit is the regulatory mechanism comprising transistors M_2 and M_3 . Transistor M_2 senses the drain to source voltage V_{ds1} of M_1 , but since M_2 carries a constant current I_{ref} any difference between V_{ds1} and the gate to source voltage needed to sustain the current I_{ref} is detected and amplified in the feedback loop comprising transistors M_2 and M_3 . Thus the drain to source voltage V_{ds1} of the memory transistor is regulated at a constant value equal to V_{gs2} . Any changes in V_{ds1} due to output voltage variations are reduced by approximately a factor of $(g_m r_{ds})^2$, and with all transistors operating in saturation this quantity can be as high as 10,000. One of the key features of this circuit is the high ratio between output and input resistances. In the track

mode, the input resistance is $1/g_m$, which is normally in the $k\Omega$ range. In the hold mode though, the output resistance is approximately $g_m^2 r_{ds}^3$, which is normally in the $M\Omega$ range. Thus carefree interconnection of modules is possible.

2.4 Summary

Oversampled delta-sigma data converters and their advantages were discussed. Due to their high linearity, reduced anti-aliasing filter complexity and high tolerance to circuit imperfections, these converters have become the method of choice for high resolution conversion of low frequency signals. This chapter also reviewed the state-of-art for bandpass delta-sigma data converters and switched-current circuits. In the remaining chapters these concepts will be combined to yield a balanced, switched-current bandpass delta-sigma modulator.

Chapter 3. The Bandpass Modulator

In this chapter the design of the bandpass delta-sigma modulator is discussed. The circuit implementation is also discussed from a high-level perspective. Lower level details will be dealt with in Chapter 4.

3.1 *N*-path Structures

In the previous chapter, the need for *N*-path structures was mentioned. The primary motivation for using *N*-path structures is that the key component of any modulator is a high quality resonator, that is, a block with poles precisely on the unit circle. In a lowpass modulator, the resonators have poles at or near $z=1$. Since the SC integrator has a pole precisely at $z=1$, this block is ideally suited for building lowpass modulators. The fact that the integrator pole is determined by the structure of the circuit and not by its component values makes the circuit tolerant of component errors. To place poles slightly offset from $z=1$, a two-integrator loop such as the one illustrated in Figure 3.1 is used. This works satisfactorily because the feedback coefficient is determined by the difference between the desired pole location and $z=1$. Writing the loop equation,

$$\frac{z}{z-1} \cdot \frac{1}{z-1} \cdot (-\gamma) = 1,$$

we find that the poles are the roots of

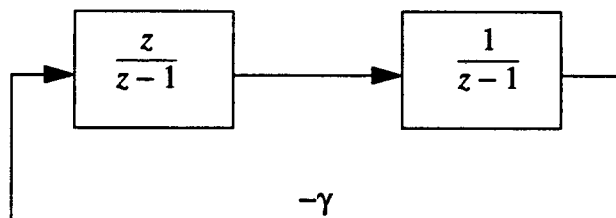


Figure 3.1: A two-integrator loop.

$$z^2 - (2 - \gamma)z + 1 = 0$$

For $\gamma > 0$, the poles are complex with real parts equal to $1 - \gamma/2$. Hence for a pole near $z=1$, γ is small. Small percentage errors in this coefficient lead to small errors in pole location. What happens when this scheme is used to implement poles elsewhere on the unit circle?

Let us consider the case where the poles have to be at $z = \pm j$. In this case $\gamma = 2$, which is no longer small compared to 1. Now a small percentage change in γ causes an equal sized change in the pole location. For an oversampling ratio of 128, γ must be accurate to a fraction of a percent. Clearly an alternative structure is needed for the realization of modulators with high oversampling ratios.

The resonator in question has a transfer function of

$$R(z) = 1/(1 + z^{-2}). \quad (3.1)$$

The corresponding time domain equation is

$$V_{out}(n) = -V_{out}(n-2) + V_{in}(n), \quad (3.2)$$

which has a form reminiscent of an integrator.

Now consider a $1/(1 + z^{-1})$ block clocked at $f_s/2$ with the clock phasing chosen so that the block is clocked on even cycles. Then, for even clock cycles,

$$V_{out}(n) = -V_{out}(n-2) + V_{in}(n), \quad (3.3)$$

and for odd clock cycles,

$$V_{out}(n) = V_{out}(n-1). \quad (3.4)$$

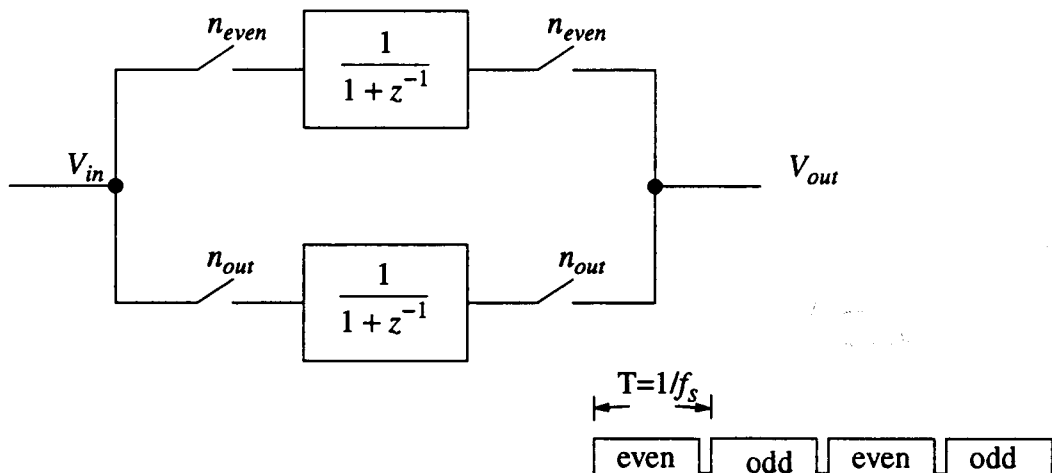


Figure 3.2: A 2-path circuit using a two-phase clock with each block clocked at $f_s/2$.

If two such blocks are connected in parallel, one which operates for even clock phases and one for odd clock phases, then the required transfer function can be obtained. This is illustrated in Figure 3.2. Here, the structure of the circuit determines the zero locations, so the zeros are almost perfectly placed. However, such a structure is very sensitive to matching between the two paths. The pseudo N -path structure [9] provides a solution to the mismatch problem by sharing hardware among the various paths.

3.2 The Modulator

An existing fourth-order lowpass modulator design [11] was modified using a $z \rightarrow -z^{-2}$ transformation to obtain a bandpass design. The lowpass design is a fourth order cascade of resonators structure, so the resulting bandpass design is eighth-order. It is illustrated in Figure 3.3. This design has been optimized and scaled with an eye for the upcoming SI implementation. In particular, some of the delays have been absorbed into the feedback path so as to arrive at a single resonator transfer function which is amenable to a switched-current implementation. A signal to noise ratio (SNR) versus input power curve

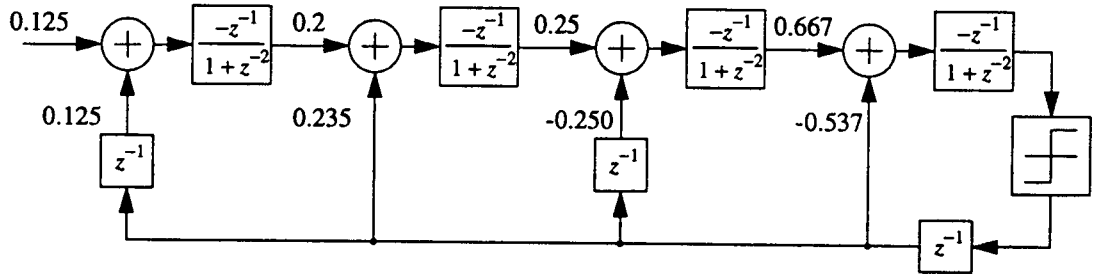


Figure 3.3: The eight-order bandpass modulator.

for an OSR of 64 is given in Figure 3.4. It is observed that the SNR peaks at 91.8dB for an input power of -9 dB where an input power of -3 dB corresponds to a full scale sine wave.

3.3 The 2-Path Resonator

The most crucial block in the entire modulator is the resonator or $\frac{-z^{-1}}{1+z^{-2}}$ block. The time domain equation for the resonator is given by

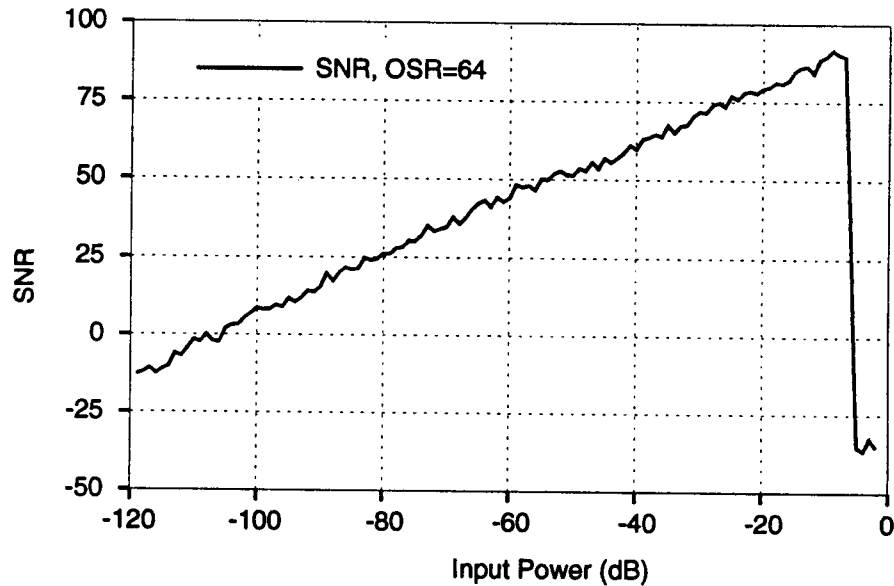


Figure 3.4: An SNR versus input power curve for an eight-order modulator.

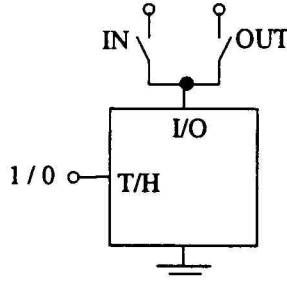


Figure 3.5: Block level model of a current memory cell (CMC).

$$i_{out}(n) = -i_{in}(n-1) - i_{out}(n-2). \quad (3.5)$$

As is evident from the above equation, some form of current memory is required to store the input and output currents from previous clock periods. For the sake of clarity, we will model the current memory cell at the block diagram level. Figure 3.5 illustrates a block level model of a current memory cell (CMC). When the T/H signal is logic 1, the cell is in the track mode. When T/H is logic 0, the cell is in the hold mode and sinks or sources the same amount of current memorized during the most recent track mode. There are two switches connected to the common I/O terminal. One switch connects the cell to the input of the resonator while the other connects the cell to the output of the resonator. Only one of the switches can be closed at any given instant.

Three of these cells can be connected in such a fashion that the resulting output current satisfies Eq. (3.5), as shown in Figure 3.6. The operation of this circuit is graphically illustrated in Figure 3.7. Consider first time cycle A. In this cycle, cell 1 is in the track mode while cells 2 and 3 are in the hold mode. Cell 3 sources the output current $i_{out}(n)$, while cell 2 is sourcing the previous output current $i_{out}(n-1)$. Cell 1 sinks the sum of the input current and the output current of cell 2, $i_{in}(n) + i_{out}(n-1)$. In the next cycle, that is, cycle B, cell 2 is in the track mode while cells 1 and 3 are in the hold mode. Cell 1 is now connected to the output and since it is in the hold mode, it sources a current

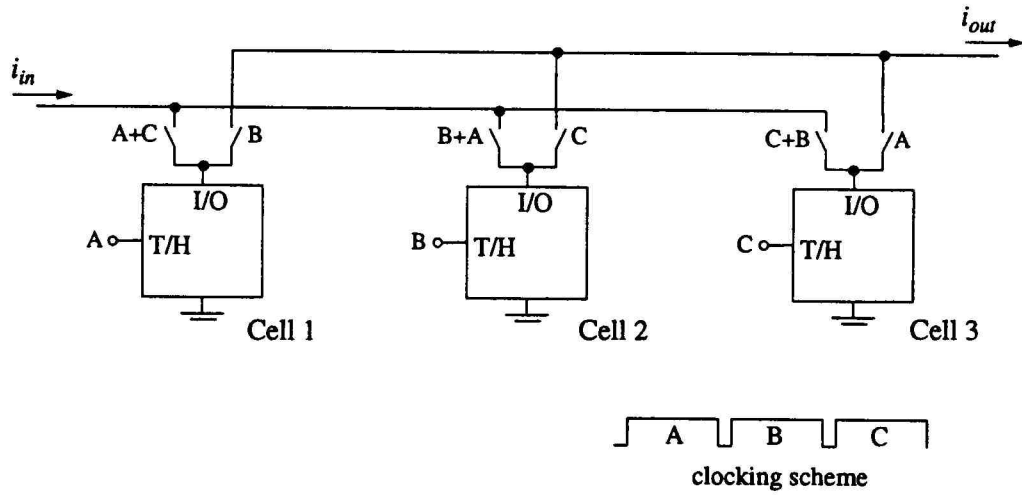


Figure 3.6: Block-level SI implementation of the bandpass resonator. The '+' sign indicates the logical OR operation.

$i_{out}(n+1) = -i_{in}(n) - i_{out}(n-1)$. This expression is essentially that given in Eq. (3.5) with n replaced by $n+1$. During this cycle, cell 2 is connected to the input and tracks a current equal to $-i_{in}(n+1) - i_{out}(n)$. In the next cycle, that is, cycle C, cell 2 will be connected to the output and will source a current $i_{out}(n+2) = -i_{in}(n+1) - i_{out}(n)$. This pattern repeats itself and thus this structure implements the desired time-domain equation. The currents are circulated between the three current memory cells and since this structure is based on a pseudo 2-path structure, the individual memory cells need not be perfectly matched with each other. This makes transistor level design much simpler.

Although the single-ended version of the resonator described above realizes the desired time domain equation, it is desirable in practical implementations to have a differential implementation. This is a result of the fact that non-ideal effects such as clock feedthrough and power-supply noise have large common-mode components which can be suppressed by using a differential structure.

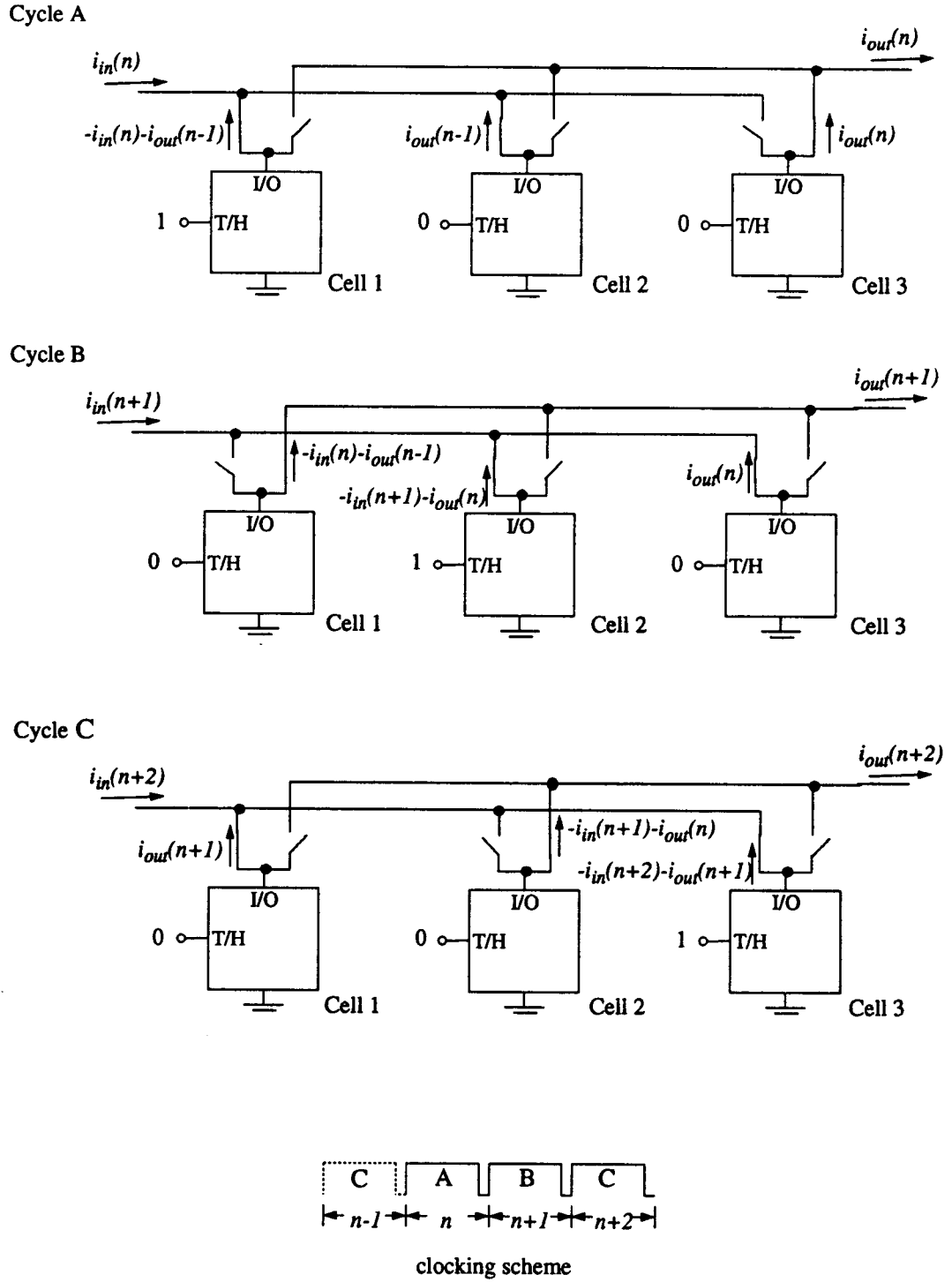


Figure 3.7: Graphical illustration of the operation of the bandpass resonator.

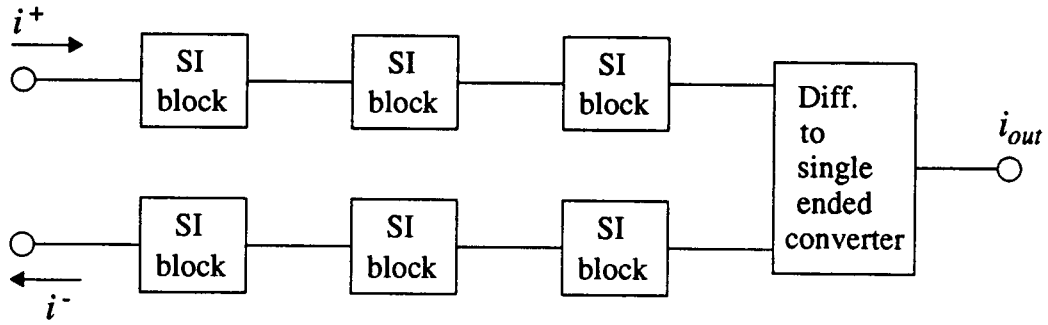


Figure 3.8: The globally differential scheme. Common mode control only at the output.

There are two ways of achieving differential operation with SI circuits. The first is the globally differential scheme, illustrated in Figure 3.8. In this scheme the two paths are distinct until the last stage, which normally is a differential to single-ended converter. The disadvantage of this strategy is that there is no common-mode control mechanism and since each block is unstable in isolation, internal states may become unbounded. It is the author's belief that this scheme is not very effective in performing common-mode rejection because it is only performed at the output.

An alternative scheme is the locally differential scheme, illustrated in Figure 3.9. Each SI block is differential in nature and hence common mode control is possible in each stage. Cascading of the common-mode errors is prevented and thus the possibility of

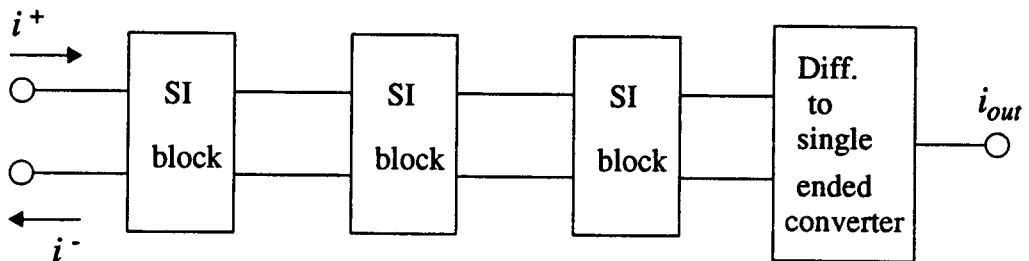


Figure 3.9: The locally differential scheme. Common mode control in each block.

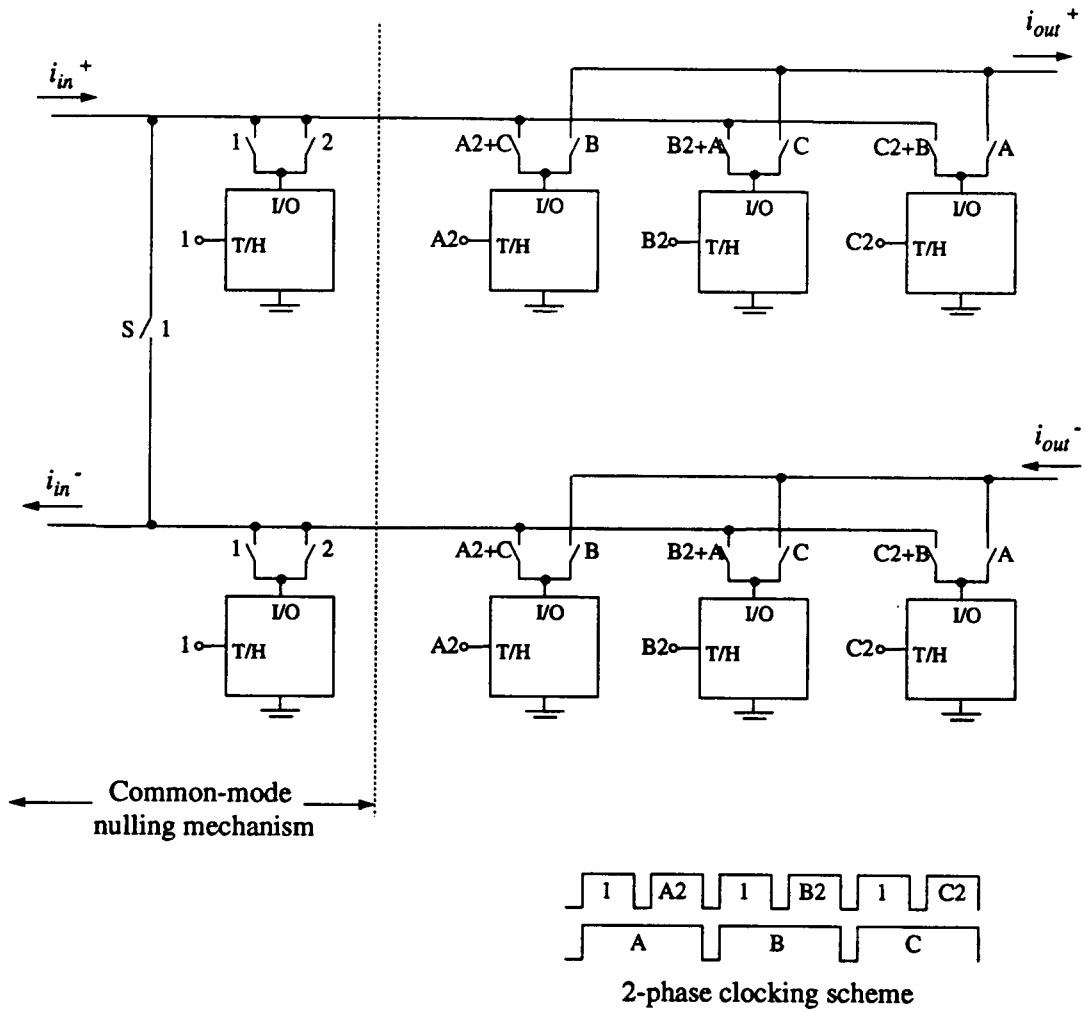


Figure 3.10: A differential SI bandpass resonator employing a common-mode nulling scheme.

internal states becoming unbounded is eliminated. The author believes that a significantly higher common mode rejection ratio (CMRR) can thereby be obtained.

A differential version of the SI bandpass resonator is illustrated in Figure 3.10. This structure employs the locally differential scheme. In order to implement common-mode control, the clocking scheme had to be modified by dividing each cycle into two phases. The memory cells are controlled such that they can track the input current only during

phase 2 of each time-cycle. Phase 1 is used for performing common-mode nulling. The structure comprises two single ended structures and some extra circuitry involving two additional current memory cells and a switch. The operation of the cell is as follows.

During phase 1 of each clock period the two halves of the circuit get connected to each other through the switch S. Any imbalance in the currents flowing in the two halves is ideally split equally between the two additional current memory cells. Such an imbalance could be a result of non-ideal effects such as clock feedthrough or mismatch between the two halves of the differential circuit. During phase 2 of each clock period the two halves are isolated from each other. Since the additional memory cells sink a current which is one half the error current, the currents flowing into both halves are equal in magnitude. Any imbalance in the currents is evened out, thereby eliminating the common-mode component.

One potential shortcoming of this structure is the need for matching between the two additional current memory cells. Since these cells need only absorb the small common-mode component, they can be made very small relative to the main cells and thus mismatch becomes a second-order effect. Also, since common-mode nulling is only needed to prevent an unrestricted build-up of common-mode current, nulling can be done infrequently, thereby reducing the errors caused by mismatch even further.

We now have a way to implement the resonator using current track and hold blocks. In the next chapter the transistor level implementation of the differential 2-path resonator will be presented.

Chapter 4. Practical Issues

This chapter discusses the circuit implementation from a transistor-level perspective. The memory cell is used to implement the resonator and the common-mode nulling scheme. Simulations show that the circuit is viable provided the common-mode sensing is done properly. The other, less critical, blocks needed in a bandpass $\Delta\Sigma$ modulator are also briefly described.

4.1 The Regulated Cascode Current Memory Cell

The regulated cascode current memory cell was introduced in chapter 2. In this section we will examine this circuit in more detail. The design and simulation results will also be presented. As was discussed earlier, to allow carefree interconnection of modules we need a circuit with a high output to input resistance ratio. An ordinary cascode scheme is not sufficient, and hence some form of a feedback loop is required. Figure 4.1 shows one way to implement such a feedback mechanism.

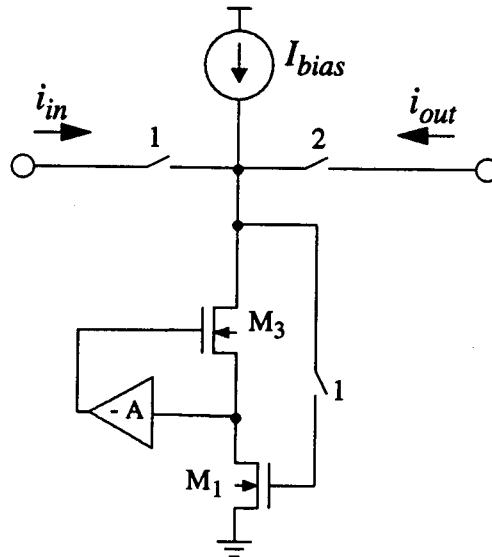


Figure 4.1: A regulatory mechanism for the dynamic current copier.

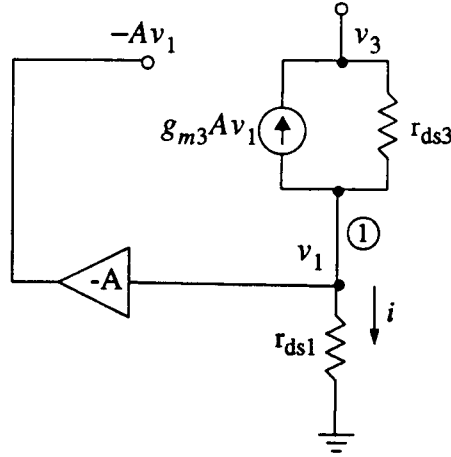


Figure 4.2: A small-signal model for the circuit in Figure 4.1.

Figure 4.2 illustrates the small signal model for this circuit in phase 2. From this figure, it can be seen that if A is large

$$v_3 \cong -g_{m3} r_{ds3} A v_1. \quad (4.1)$$

Since, $i = v_1 / r_{ds1}$,

$$R_{out} = \frac{v_3}{i} \cong g_{m3} r_{ds3} A r_{ds1}. \quad (4.2)$$

The amplifier can be implemented by a MOS transistor with a current source load, yielding the regulated cascode current memory cell [13] shown in Figure 4.3. Here transistor M_2 acts as an amplifier. Assuming the current source is ideal, the gain A of this transistor is $g_{m2} r_{ds2}$. Thus the output resistance of the cell is now $g_{m3} r_{ds3} g_{m2} r_{ds2} r_{ds1}$ and an output to input resistance ratio of more than 10^4 can be easily achieved.

A small-signal model for the settling behavior of this circuit is fairly complex due to the presence of a feedback loop and three potentially significant gate-to-source

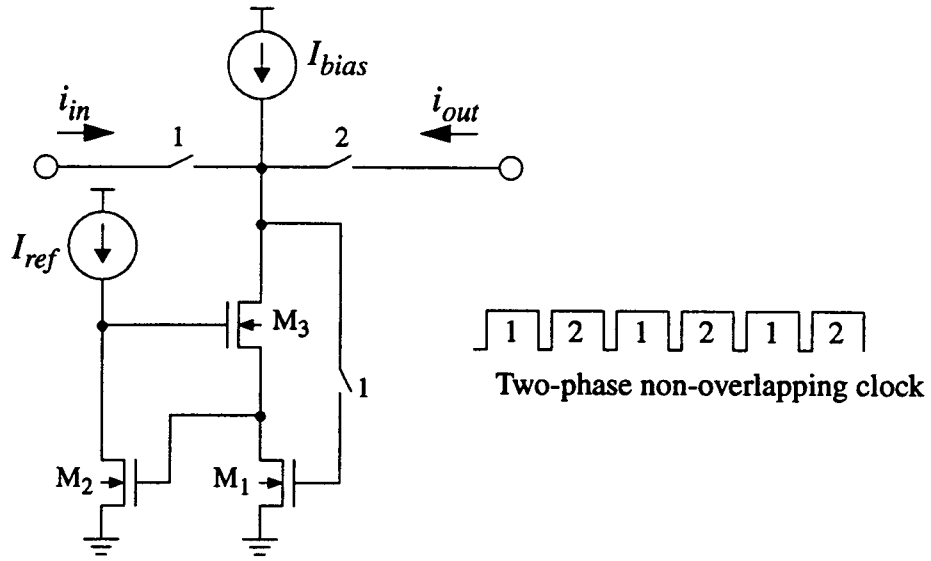


Figure 4.3: The regulated cascode current memory cell.

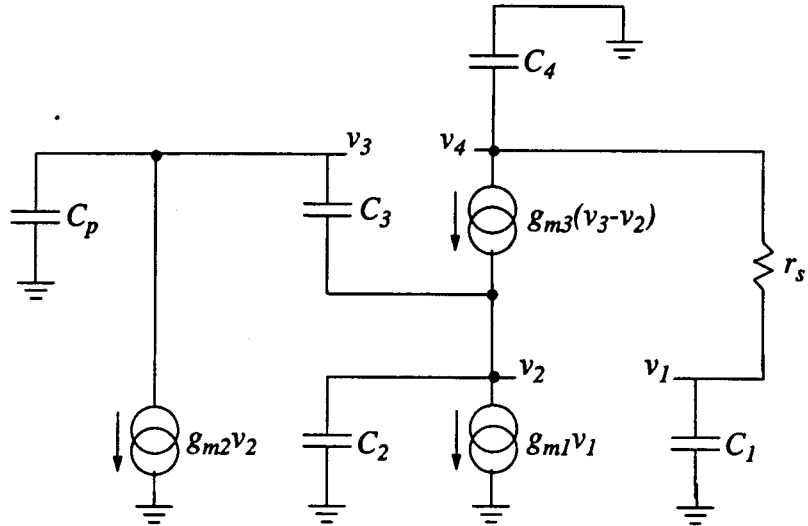


Figure 4.4: Small-signal model of the regulated cascode current memory cell for the settling time analysis.

capacitances. A complete analysis of the dynamics of this circuit yields the following fourth-order system:

$$s \begin{bmatrix} v_1 \\ v_2 \\ v_3 \\ v_4 \end{bmatrix} = \begin{bmatrix} \frac{-g_s}{C_1} & 0 & 0 & \frac{g_s}{C_1} \\ \frac{g_{m1}}{C_2} & \frac{-g_{m3}}{C_2} & \frac{g_{m3}}{C_2} & 0 \\ -k \frac{g_{m1}}{C_2} & -k \left(\frac{g_{m2}}{C_3} + \frac{g_{m3}}{C_2} \right) & k \frac{g_{m3}}{C_2} & 0 \\ \frac{g_s}{C_4} & \frac{g_{m3}}{C_4} & -\frac{g_{m3}}{C_4} & -\frac{g_s}{C_4} \end{bmatrix} \begin{bmatrix} v_1 \\ v_2 \\ v_3 \\ v_4 \end{bmatrix} \quad (4.3)$$

where

$$k = \frac{C_3}{C_3 + C_p}. \quad (4.4)$$

The C_p capacitance is a parasitic capacitance which has been found to have a strong effect on the dynamics of the system. The poles of the system are the eigenvalues of the above matrix. Assuming that this system has a dominant pole with associated time constant τ , the time required for 0.1% settling will be

$$t_s = 7\tau. \quad (4.5)$$

Due to the form of the elements in the matrix of Eq. (4.3), τ is proportional to the C/g ratios in the circuit and thus the circuit should be able to settle very quickly. The impact of using a shorter-channel process is also immediately obvious from this observation: settling time will decrease in inverse proportion to L^2 , thus making this circuit attractive for high speed applications. A comparison of the predictions given by this model and simulation results are given later in the chapter.

The circuit shown in Figure 4.3 suffers from several non-ideal effects. In a practical implementation the switches are replaced by MOS transistors as shown in Figure 4.5.

In Figure 4.5, the data storage node is the gate terminal of the memory transistor M_1 . When memory switch S_m opens, some of the channel charge is injected into the gate terminal of M_1 , thereby superimposing an error component ΔV on the voltage already stored on C_{gs1} . Due to this error component, the current through the cell during the hold phase is not equal in magnitude to the input current. Several schemes exist which address this problem. The first method is to increase the value of C_{gs1} . Since $V = \frac{Q}{C}$, any increase in the capacitance results in a decrease in the error voltage ΔV . Increasing the value of C_{gs1} though, results in an increase in the settling time. Clearly for high clock frequencies this scheme is not very practical.

A second possibility is the use of dummy switches [2]. In this scheme a dummy transistor S_d with its drain and source shorted, and a complementary gate signal, $\bar{1}$, is inserted between the switching transistor S_m and the data node. To ensure the best possible compensation, the dummy switch is half the size of the main switch and is as close as possible to the main switch in the actual circuit layout. This kind of compensation does reduce the charge injection by at least one order of magnitude. Other possibilities include the use of a staggered clocking scheme and coarse/fine memories [4].

One of the problems encountered during simulation was that when the input switch and the memory switch were opened at the end of phase 1, a large error voltage was added to the voltage already held on the gate of the memory transistor. The reason for this is that when these switches were turn off, the input current no longer balances the cell current and the voltage at the drain of transistor M_3 changes rapidly. Due to the finite switching time of the memory switch S_m , the data node is still connected to the drain of M_3 and hence the sampled voltage V_{gs1} is affected. Thus the value of current memorized by the cell is erroneous. This problem was overcome by tinkering with the clocking scheme. As is shown in Figure 4.5 the memory switch is now clocked by phase 1' (1 prime) which falls to zero

before phase 1. The memory switch is now opened before the input switch, and so isolates the data node from the rest of the circuit. Thus any change in the voltage at the drain of M_3 does not affect the sampled voltage V_{gs1} . The input and output switches, namely S_{in} and S_{out} , are implemented as CMOS switches or transmission gates. This has been done in order to ensure low on-resistance under all operating conditions.

The design of this cell was done keeping in mind the various compensation schemes that had to be used. The cell was designed for an input current range of $\pm 100\mu A$ and a clock frequency of 10 MHz. The design was done so that the voltage at the drain of transistor M_3 is limited to the range of 1.5 - 3 Volts. This upper limit ensures that the bias current source transistors are maintained in saturation. The memory switch size has been kept as small as possible. The minimum transistor width that the Mosis SCMOS process permits is 4 microns. Since the dummy switch S_d is half the size of the memory switch S_m , the minimum dimensions that transistor S_m could have are 8 microns by 2 microns. The input and output switches are made wide and short in order to keep the voltage drops across these transistors to a minimum. The current sources I_{bias} and I_{ref} have been implemented as regulated cascode current sources and are biased using a totem-pole transistor structure. These current sources have a very high output resistance and thus provide a stable and accurate source of current.

The transistor sizes for the regulated cascode current cell are given in Table 1. The dimensions of the memory transistor M_1 are determined by two factors, one is the transconductance g_m of the transistor and the other is the gate to source capacitance C_{gs1} . Having a very high value of transconductance is undesirable since it tends to increase the effect of clock feedthrough. On the other hand increasing the value of C_{gs1} tends to suppress the effect of clock feedthrough but increase the settling time, thereby reducing the maximum frequency of operation. A good design has to strike a balance between these two

factors. In this case a combination of a dummy switch and twice the minimum length

Table 1: Transistor dimensions

Transistor	Width in microns	Length in microns
M_1	28	4
M_2	60	2
M_3	80	2
S_m	8	2
S_d	4	2
S_{in}	20	2
S_{out}	20	2

memory transistor provided a satisfactory amount of clock feedthrough suppression. The factor that influenced the dimensions of the remaining two transistors was the need for regulating the drain voltage of transistor M_1 . illustrates the voltage regulation mechanism of this cell. The voltage at the drain of M_1 , V_{ds1} , is not affected by the variations in the output voltage V_{d3} . Thus, the influence of channel length modulation on the current flowing through the cell is prevented.

Figure 4.7 illustrates the current versus time curves for a 5 MHz square wave input. The cell is clocked at 10MHz. Notice that the input is sampled during phase 1 and that the output is held at the sampled value during phase 2. The slight discrepancy between the desired and the actual value of output current is due to residual clock feedthrough. Figure 4.8 illustrates the output response for a sinusoidal input. Here both the continuous-time and the discrete-time input current signals have been illustrated. Notice that the sample and hold operation is inherent to the current memory cell.

In order to measure the settling time of the circuit, two current memory cells clocked in opposition are connected in such a fashion that the output of the first cell forms the input to the next. The first cell tracks an input current of $100\mu\text{A}$ during phase 1. During phase 2, cell 1 is in the hold mode and sources a current close to $100\mu\text{A}$, which in turn is tracked by cell 2. The time required for this current to settle to within 0.1% of its final value is the settling time of the circuit. Simulations measure this time at 10 ns, which is quite close to the theoretical value of 10.2 ns predicted by Eq. (4.5) when the HSPICE-determined parameters were fed into Eq. (4.3). These numbers indicate that this circuit could be operated at frequencies approaching 50 MHz. Appendix B contains a listing of the HSPICE output files for the regulated cascode current memory cell.

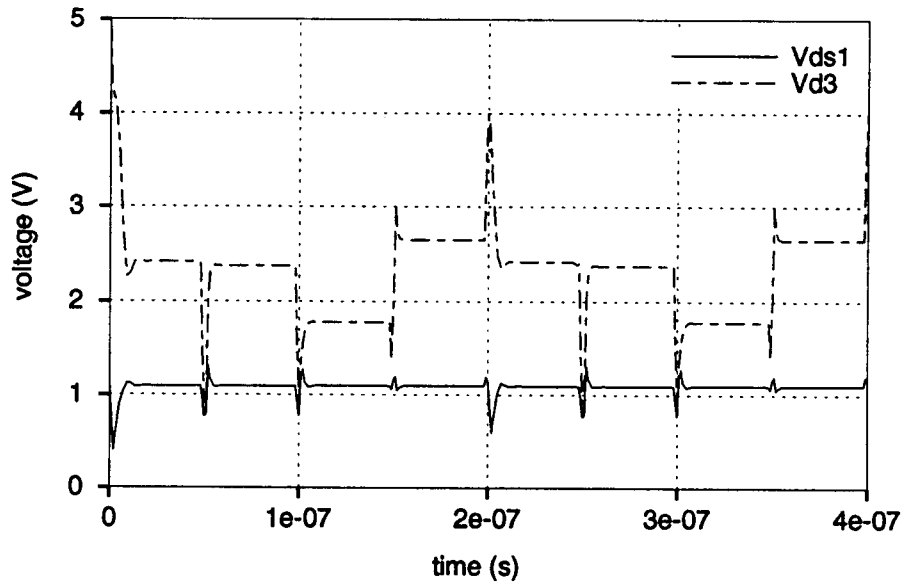


Figure 4.6: Regulation of the drain voltage V_{ds1} of transistor M_1 , independent of the variations in the output voltage V_{d3} .

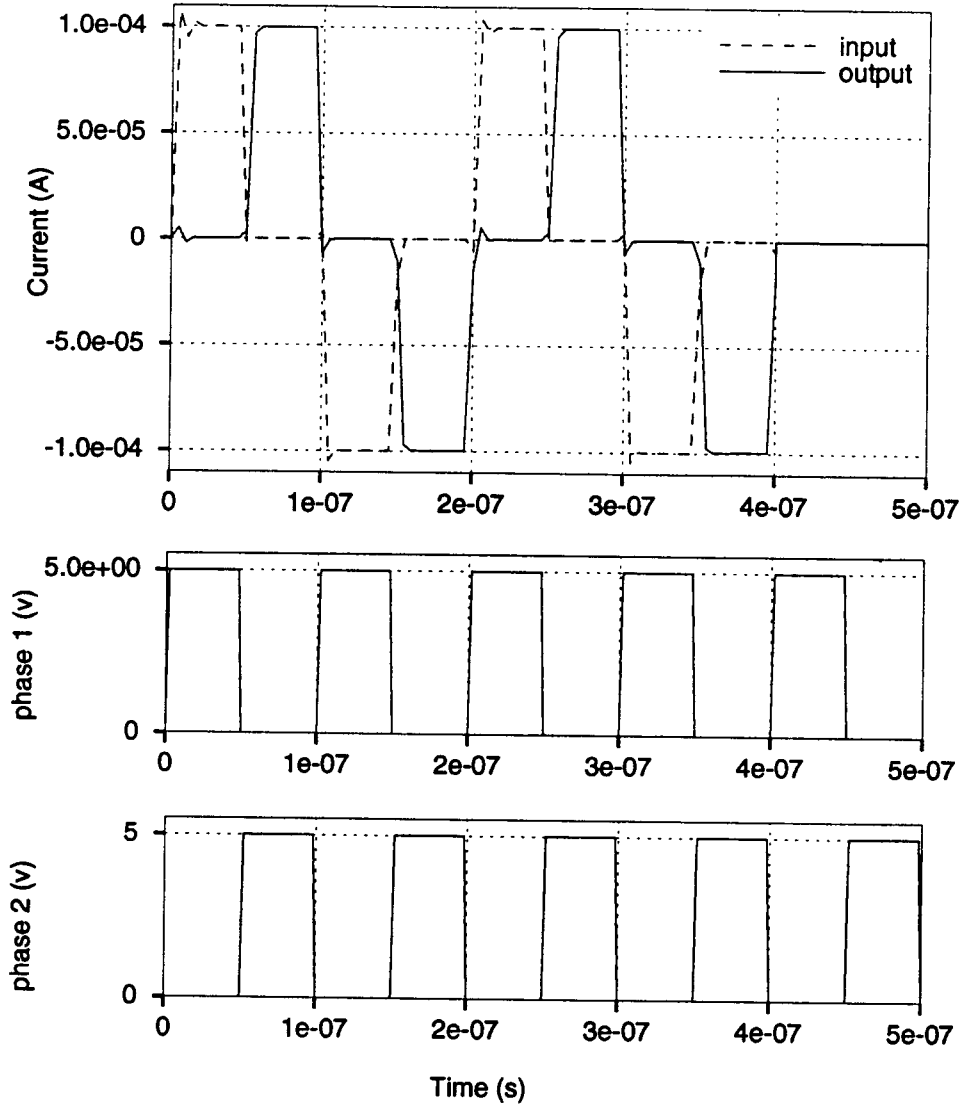


Figure 4.7: Current versus time curves for a 5 MHz, 200 μ A (peak to peak) squarewave input.

4.2 The Differential SI 2-Path Resonator

In the previous sections we discussed the design and operation of the regulated cascode current memory cell. This cell is used as the basic current memory cell in the design of the resonator.

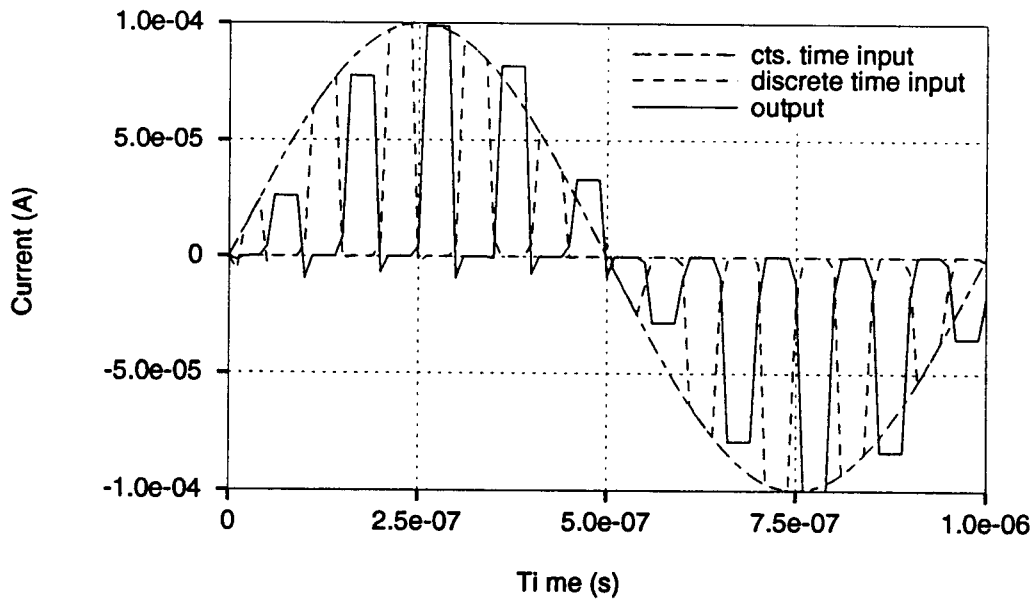


Figure 4.8: Current versus time curves for a 1MHz, 200 μ A sinusoidal input.

In Section 3.3 the block-level implementation of the resonator was presented. The current memory blocks in that design need to be replaced with regulated cascode current memory cells in order to get a transistor-level design. This circuit is illustrated in Figure 4.9. As is evident from the figure, the basic topology remains the same, but there are some minor modifications within the common-mode nulling block. Since a MOS switch has a nonzero “ON” resistance, a small voltage drop appears across it during phase 1 when the differential current is flowing through it. This results in a voltage differential between the two input terminals of the common-mode nulling current memory cells, causing unequal currents to flow through them. In order to solve this problem an idea similar to Kelvin sensing is employed. The switch connecting the two halves is replaced by the more elaborate network of switches shown in Figure 4.9. During phase 1 the input terminals of the two common-mode nulling current memory cells are connected by a virtual short, thus ensuring that there is no voltage drop between the I/O terminals. Equal amounts of current flow into each cell thus ensuring good common-mode nulling.

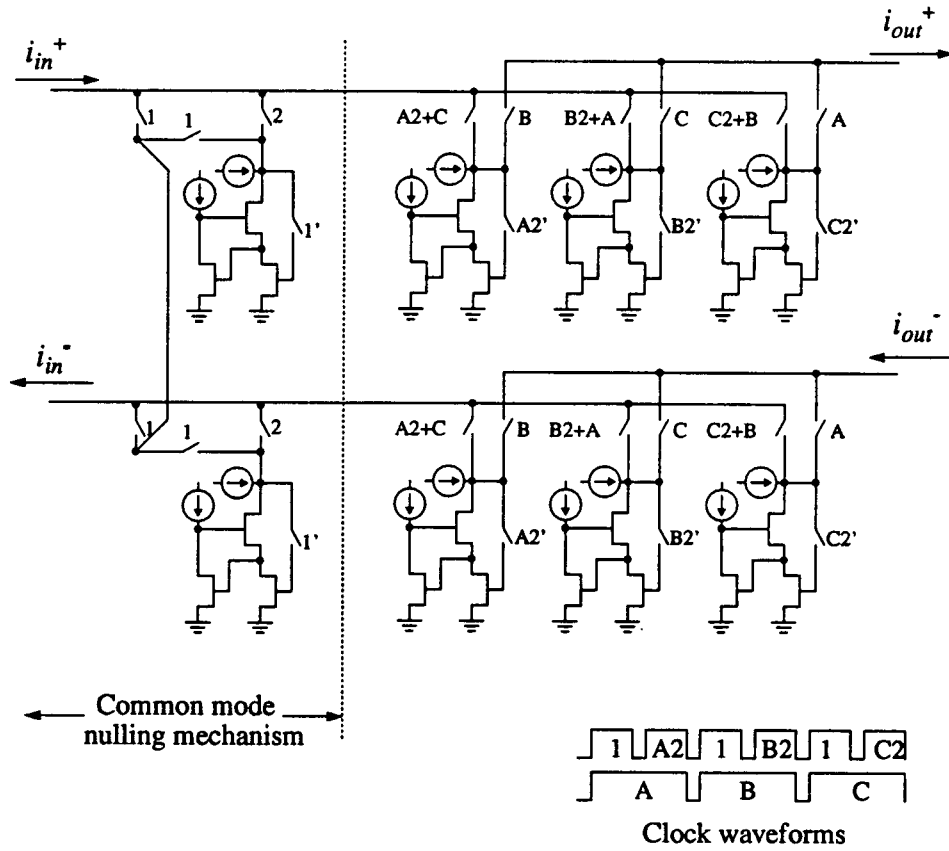


Figure 4.9: A differential switched-current 2-path resonator with improved common-mode nulling.

Figure 4.10 illustrates the impulse response of a single ended 2-path resonator. The $100\mu\text{A}$ input current pulse results in alternating output current pulses occurring on odd clock cycles, which is in accordance with the time domain equation of Eq. (3.5). Compare this with Figure 4.11 which illustrates the current versus time curves for a differential 2-path resonator. To demonstrate the common-mode nulling mechanism, i_{in}^+ is made greater than i_{in}^- by $20\mu\text{A}$. As can be seen from the graph, the difference in the input current is evened out and the output currents in the subsequent cycles are balanced. The output waveform therefore has the desired differential behavior with a common-mode component equal to zero.

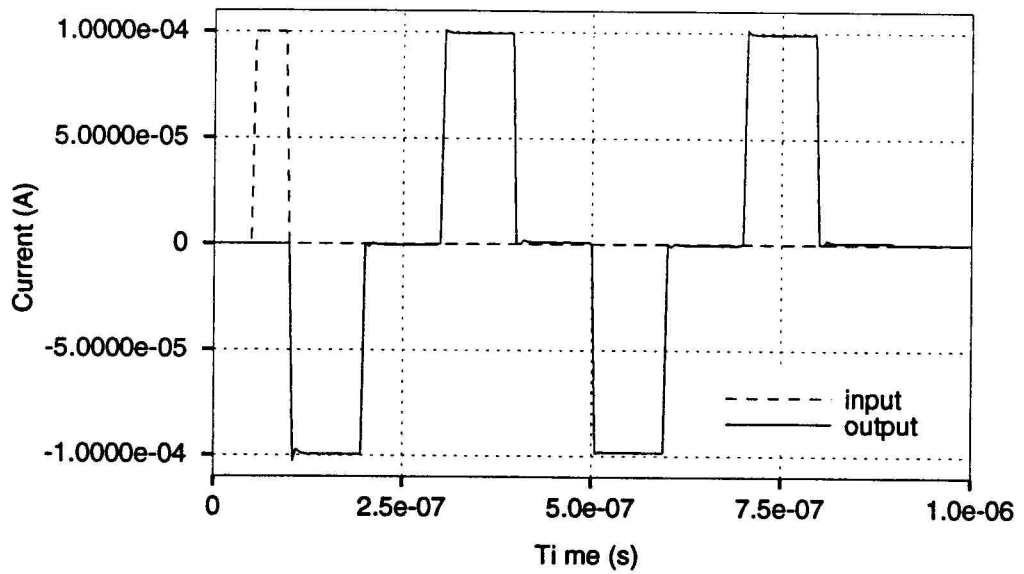


Figure 4.10: Impulse response of a single ended switched-current 2-path resonator.

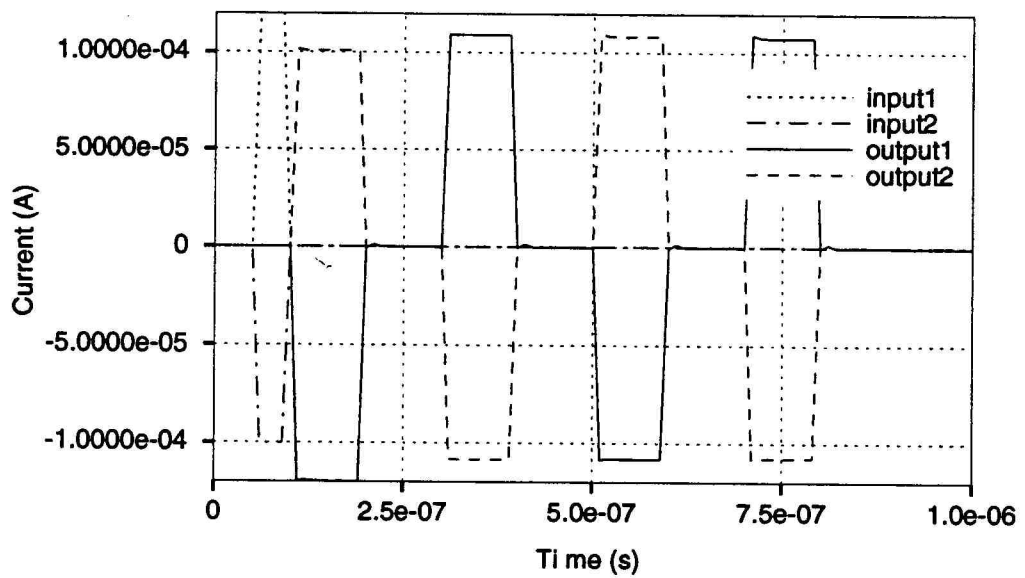


Figure 4.11: Impulse response of a differential switched-current 2-path resonator.

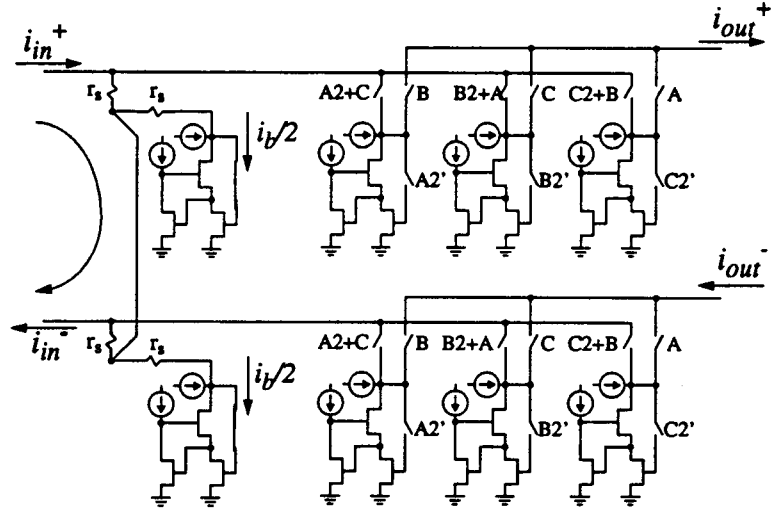
The operation of the common-mode nulling mechanism is graphically illustrated in Figure 4.12. Let i_{in}^+ be greater than i_{in}^- by an amount equal to i_b , where i_b is the imbalance in the current due to non-ideal effects. During phase 1 of each cycle, the two halves are shorted to each other and the error current is equally distributed between the two common-mode nulling current memory cells. During phase 2 these cells hold the current memorized during phase 1 and thus even out the imbalance between the input currents.

A key feature of this circuit is that the output current is available in both the clock phases, thus making common-mode nulling feasible. The disadvantages are the complexity of the clocks and the requirement for matching between the common-mode nulling memory cells. As can be seen from the circuit, the clocking is fairly complex. We need 12 distinct clocks and their complements since most of the switches are implemented as transmission gates. For good common-mode rejection, the two common-mode nulling blocks have to be perfectly matched with each other since mismatch between the two cells results in uneven currents flowing through the two halves. Special layout techniques must be relied upon to achieve the required matching.

4.3 The Current Comparator

One of the blocks needed to build a delta-sigma modulator is the single-bit quantizer, which in this case is a current comparator. Figure 4.13 shows one potential implementation. It consists of two inverters connected in a back to back configuration. During phase 1, switch S is closed so as to equalize the voltages at the input and output of both inverters. During phase 2, the switch is opened. Imbalance caused by the currents being fed into the gates of the two inverters will cause the output voltage to settle to either logic '1' or '0' extremely quickly.

Phase 1



Phase 2

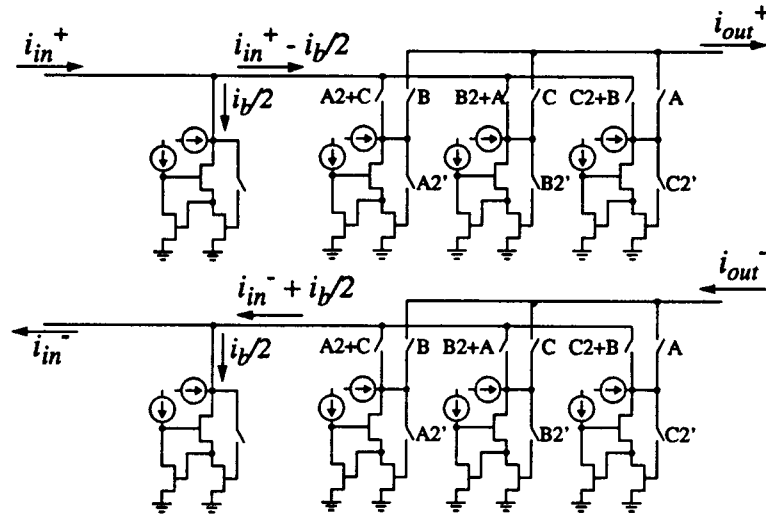


Figure 4.12: Operation of the common-mode nulling mechanism during phases 1 and 2. Here $i_{in}^+ = i_{in}^- + i_b$, where i_b is the error current.

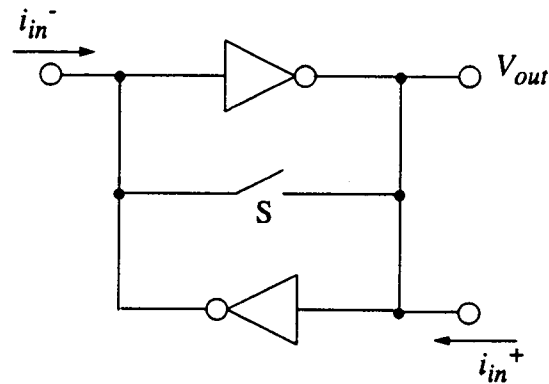


Figure 4.13: A current comparator.

4.4 The SI Digital to Analog Converter

The other auxiliary block required is the single-bit switched-current digital to analog converter (DAC). Here the digital input is a voltage signal, while the analog output is a current signal whose polarity depends upon the polarity of the input digital voltage. This block can be implemented as shown in Figure 4.14. The circuit consists of two current sources and four switches connected in a cross coupled configuration. The current sources

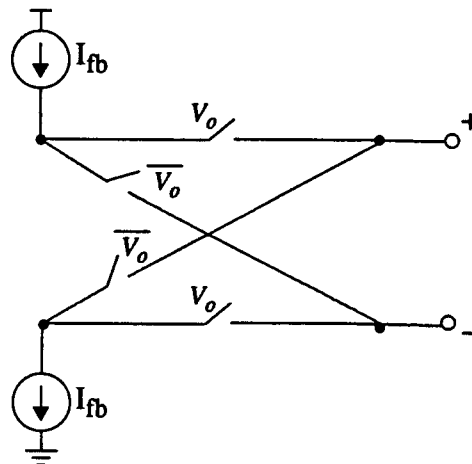


Figure 4.14: A 1-bit differential switched current D/A converter.

are implemented using regulated cascode current sources. The high output resistance exhibited by such current sources enables their easy connection to the low resistance input of the resonator. The switches are clocked by the digital output voltage V_o of the modulator. Due to the cross coupled switch configuration, the polarities of the feedback currents can be controlled by the value of the digital voltage V_o .

4.5 Clock Generation

In the previous section the need for non-overlapping and complementary clock signals was noted. These signals can be divided into two types, basic and derived. The basic clock signals are phases 1 , 2 , A , B , C . These signals are derived from a master reference clock signal. As is observed from Figure 4.9, the memory switches need to be opened prior to the input switch. These switches are clocked by either $1'$ (1 prime) or a signal derived from $2'$ (2 prime). Since $2'$ is the more widely used signal amongst the two, it is the first signal to be generated from the master clock signal. Using the logic illustrated in Figure 4.15, signal $1'$ is also generated. The cross-coupled logic ensures non-overlap between the two signals. Signals 1 and 2 can then be generated by delaying $1'$ and $2'$ by a

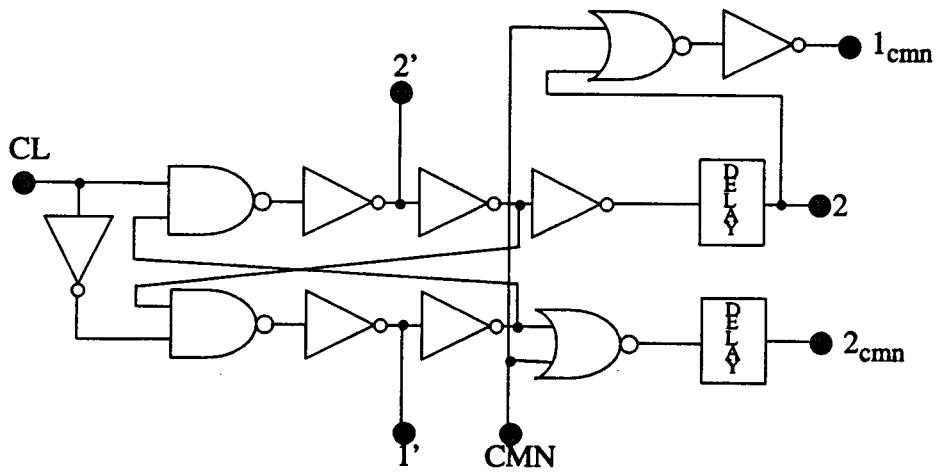


Figure 4.15: Logic circuit for generation of clock signals 1 , 2 , $1'$, $2'$, 1_{cmn} and 2_{cmn} .

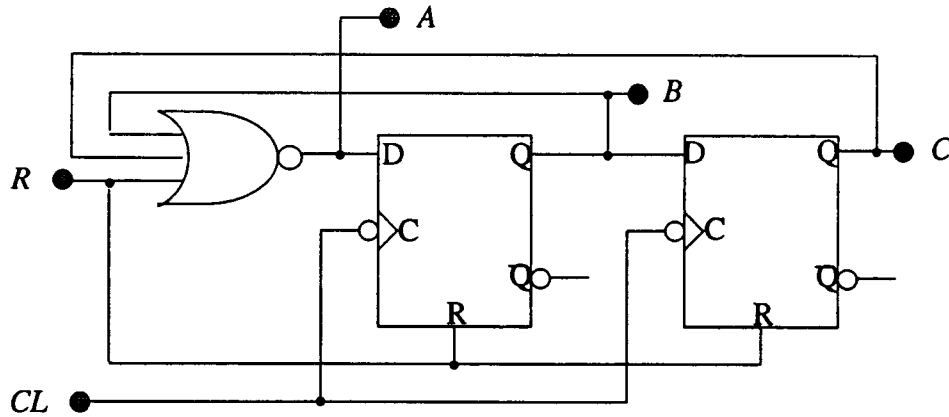


Figure 4.16: Logic circuit for generation of clock signals *A*, *B* and *C*

few gate delays so as to obtain a few nanoseconds delay. This structure also provides the complements of the various signals. The rest of the basic signals are generated using the logic illustrated in Figure 4.16. These signals need not necessarily be non-overlapping. As long as the memory switch in each cell is opened before either the input switch opens or the output closes, overlap is permissible. The rest of the signals such as $A2'$, $A2+C$, $B2'$, etc. are derived from the basic signals by means of simple combinational logic gates. The resulting waveforms are illustrated in Figure 4.17. Provision has been made for a reset signal *R* and a common-mode nulling disable signal *CMN*. The *CMN* signal controls the input and the output switches of the common-mode nulling current memory cells. Making *CMN* active, that is high, disables the common-mode nulling mechanism.

4.6 The Second-Order Bandpass Modulator

Due to lack of time the entire eight-order modulator could not be laid out. Instead, a second-order bandpass modulator comprising a resonator, the current comparator, 1-bit current DAC and supporting clock generation logic was laid out in a Tiny Chip. The block diagram for the second-order modulator is shown in Figure 4.18.

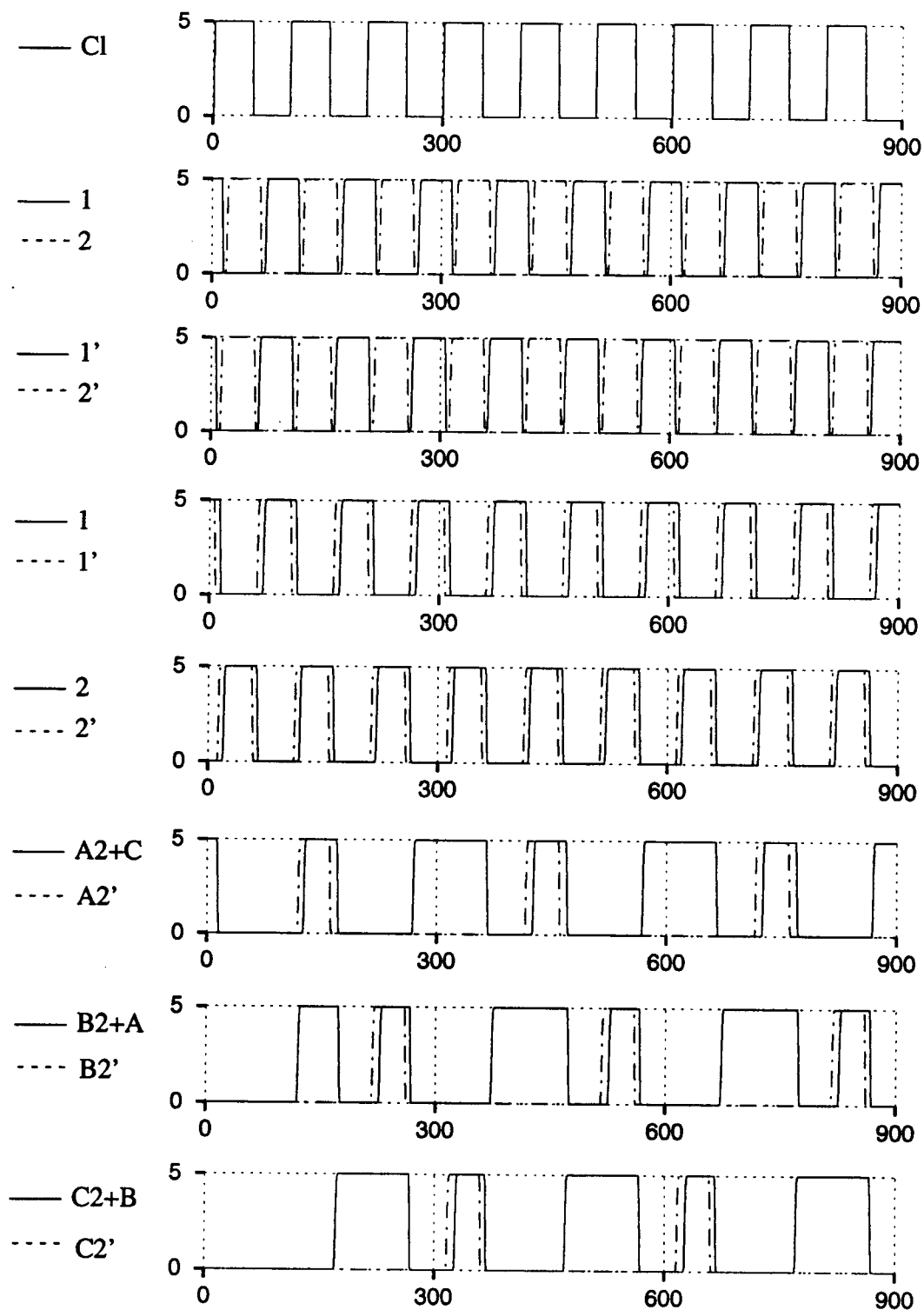


Figure 4.17: Clock waveforms for the 2-path resonator.

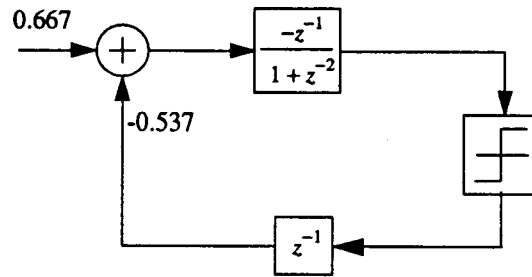


Figure 4.18: A second-order bandpass modulator.

4.7 Layout Considerations

In section 4.2 the differential switched-current 2-path resonator was discussed. The need for matching between the two common-mode nulling current memory cells was explained. This has been addressed by careful layout of the circuit. The approach is to match every transistor with its counterpart from the other cell. This can be accomplished by adopting the comb or the inter-digitated arrangement [8]. In this type of layout, the transistors are broken up into smaller sized equal width transistors. For two transistors that share a common source terminal, the source is laid out in a serpentine fashion. The two drain and gate regions are then laid out alternately such that any gradient due to process variations affects both the transistors equally. Dummy transistors are used at each end of the structure. Thus each transistor in the structure has similar shaped structures on either side and sees the same amount of capacitance on either side. Though only the two common-mode nulling cells need to be matched, the layout strategy explained above was applied to all the cells, ensuring matching between the two halves of the differential structure.

The switches on the other hand are so laid out that the clock lines can be brought out on one side of the circuit. Clock lines and signal lines have been kept as far as possible from each other. Metal lines connected to ground are laid out between any two signal lines. This ensures that there is no coupling between the lines. The memory switch and the

dummy switch are laid as close to each other as possible. The process used for the layout is a 2-micron p-well process. This process has been chosen because the crucial n-channel transistors can then be placed in a p-well, which can be then biased to ground. This limits the substrate noise injection. Guards rings are used to isolate the analog and digital circuitry. Separate power supplies connections for the analog and digital sections are also used in order to reduce the noise through power supply coupling. Appendix A contains plots of the layout. As can be seen from the plots, the layouts of the cells are quite complex and this is the price one has to pay for simplicity in design.

Chapter 5. Conclusions

This chapter summarizes the contributions of this thesis, and outlines possible directions for future work.

5.1 Summary

Chapter two presented a brief introduction to oversampling delta-sigma modulation. Bandpass $\Delta\Sigma$ conversion was introduced as a modification of lowpass $\Delta\Sigma$ conversion, and its application in conversion of narrow-band signals at high frequencies was discussed. Switched-current circuits were presented as an alternative to switched-capacitor circuits for use in analog signal processing applications. Various switched-current circuit structures were examined for their feasibility in practical implementations.

Chapter three looked at the system level design concerns of the bandpass modulator. The various modulator structures were examined, and the need for pseudo N -path structures was emphasized. The design of the bandpass modulator from its lowpass prototype was briefly discussed. The bulk of the chapter dealt with the switched-current implementation of the modulator structure. A block level design approach was adopted and a new SI architecture for the pseudo 2-path resonator was developed.

Chapter four dealt with the transistor level implementation of the SI resonator and the other auxiliary blocks. The regulated cascode current memory cell was analyzed and the simulation results presented. The problems faced in SI circuit design due to non-idealities were enumerated and circuit techniques to work around these problems were explained. The main contribution of this thesis was the development of the differential SI 2-path resonator. This resonator uses dynamic current copiers and hence overcomes to a large extent the device matching problems faced by earlier generation resonator designs.

The clock generation circuitry and layout issues were also discussed. The beauty of this design is that the use of the basic cell throughout the entire circuit makes the circuit modular. This technique can be easily generalized to implement transfer functions of the form $\frac{1}{1 + z^{-N}}$.

It has been demonstrated via simulation that switched-current circuits can be used to make bandpass delta-sigma modulators. The circuit presented here is nominally capable of being clocked at 50 MHz. Another feature of this design is its ability to use a standard digital CMOS process. The disadvantages of this approach are the lack of accuracy and the high power consumption (9 mW per resonator).

5.2 Future Work

Although a new SI architecture has been developed, there still remains a lot to be done. The higher-order modulator needs to be completed, fabricated and tested for accuracy. Converting the design to a $1\text{ }\mu\text{m}$ or a sub-micron technology could mean smaller chip sizes and higher operating speeds. The author believes that by using shorter device lengths the clock frequency could be beyond 100 MHz, which by present day standards is difficult even in switched-capacitor circuits. Another area of research is the scalability of the circuit to lower voltage operations, which could lead to lower power consumption. Better clock feedthrough cancellation schemes or design techniques which cope with the problem are also needed. The effect of thermal noise on these circuits likewise needs to be investigated. Lastly a structured methodology for the design and optimization of SI circuits needs to be developed and documented.

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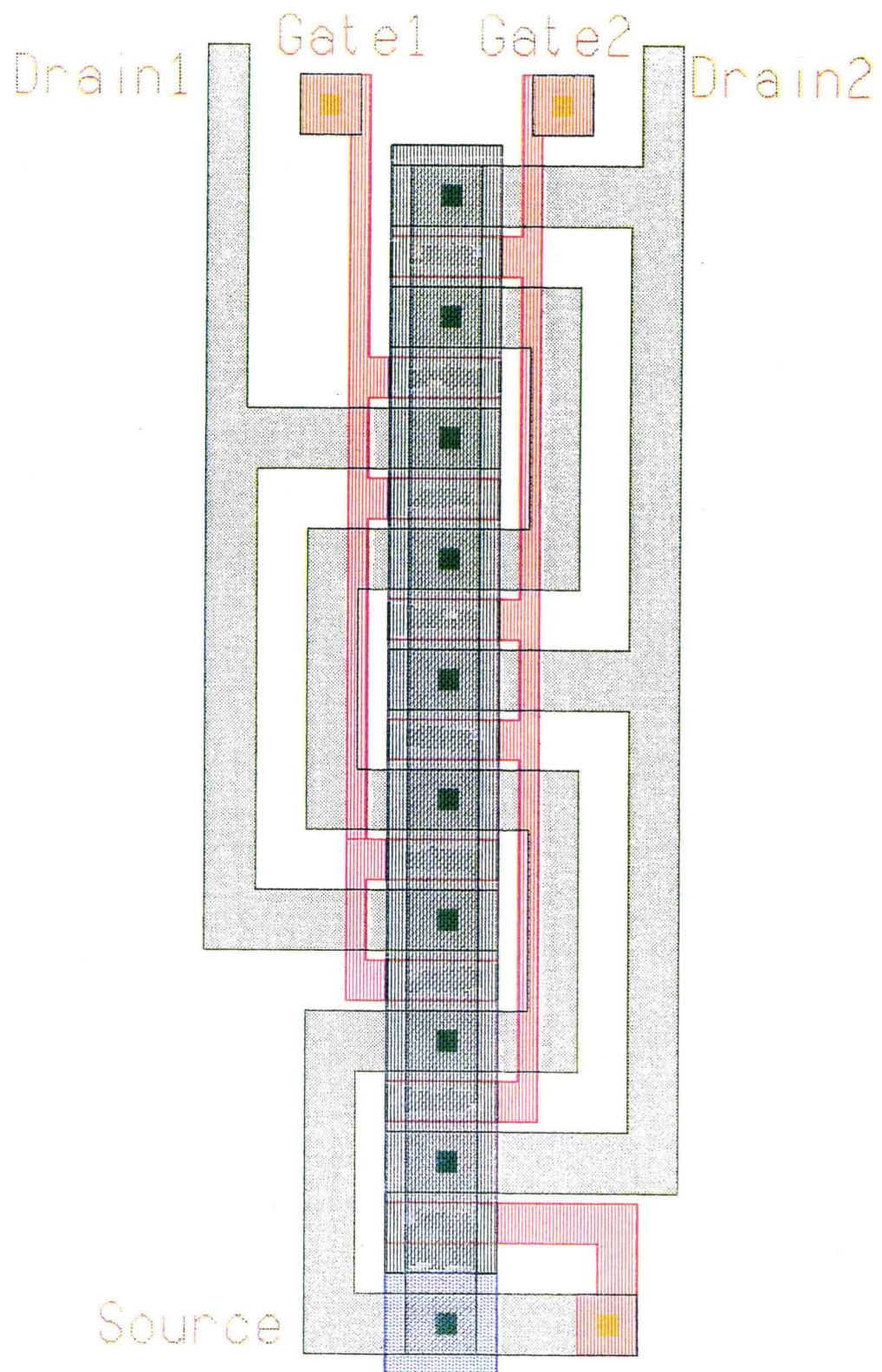
APPENDICES

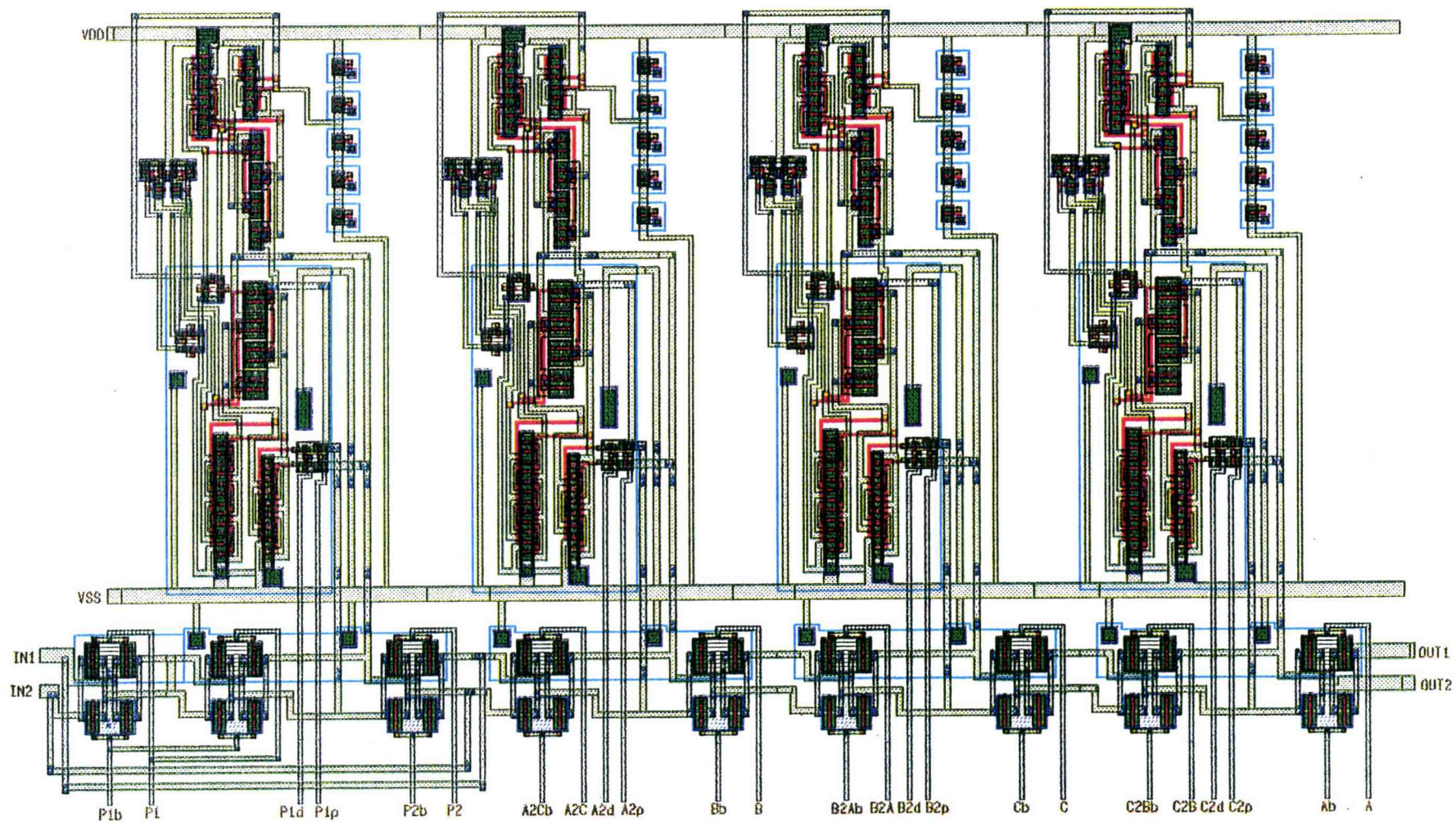
Appendix A

The plots of the layout are illustrated on the following pages.

The first plot is that of the interdigitated layout of a differential pair. Note that the source for both the transistors is common and is laid out in a serpentine fashion. The two drain and gate regions are interdigitated for matching purposes. Dummy transistors are used at each end.

The second plot illustrates the layout of the differential pseudo 2-path resonator. The clocks busses are brought out on one side for easy connection. The n-channel transistors are placed in a p-well that is connected to V_{ss} .





Appendix B

Selected parts of the HSPICE output file for the transient simulation of the regulated cascode current memory cell are listed below. Parameters values from the operating point analysis were substituted in Eq. (4.3) in order to compute the settling time of the circuit.

```
* the regulated cascode current copier
***** copyright 1990 meta-software, inc. *****site:
***** input listing
*****

.include '~/hspice/models/pwell_bsim.1'      $ include model file
.include '~/bpsd/layout/clock.10mhz'        $ include clocks
.include '~/hspice/stage/options'            $ include options file

.global vdd

.subckt irc io scale=1                        $ iref subcircuit
m1 d1 gate vdd vdd pc1_pm1_du2 w=4u l=2u
m2 g3 d1 vdd vdd pc1_pm1_du2 w=8u l=2u
m3 d3 g3 d1 d1 pc1_pm1_du2 w=8u l=2u
m4 g3 g4 s4 s4 pc1_nm1_du1 w=4u l=2u
m5 s4 s4 0 0 pc1_nm1_du1 w=4u l=2u
vg4 g4 0 3
vgg gate 0 3.3
vrc d3 io 0
.ends

.subckt ibs io                               $ ibias subcircuit
m1 d1 gate vdd vdd pc1_pm1_du2 w=27u l=2u
m2 g3 d1 vdd vdd pc1_pm1_du2 w=40u l=2u
m3 d3 g3 d1 d1 pc1_pm1_du2 w=40u l=2u
m4 g3 g4 s4 s4 pc1_nm1_du1 w=4u l=2u
m5 s4 s4 0 0 pc1_nm1_du1 w=4u l=2u
vg4 g4 0 3
vgg gate 0 3
vbs d3 io 0
.ends

.subckt switch i1 i2 c1 c2                   $ cmos switch
msn i1 c1 i2 0 pc1_nm1_du1 w=20u l=2u
msp i1 c2 i2 vdd pc1_pm1_du2 w=20u l=2u
.ends

.subckt cth_0.1m i o cm1 cm2                 $ reg. cascode c.c.
m1 d1 g1 0 0 pc1_nm1_du1 w=28u l=4u          $ memory transistor
m2 g3 d1 0 0 pc1_nm1_du1 w=60u l=2u
m3 d3 g3 d1 d1 pc1_nm1_du1 w=80u l=2u
ms_sw g1 cm1 d3 0 pc1_nm1_du1 w=8u l=2u      $ memory switch
ms_sw_d g1 cm2 g1 0 pc1_nm1_du1 w=4u l=2u    $ dummy switch
xirc g3 irc
xibias io ibs
vmem io d3 0
```

```

vin i io 0
vout io o 0
.ends

* circuit description
xcth1 in1 o1 plne p2ne cth_0.1m          $ cmc #1
xcth2 in2 o2 plpe p2pe cth_0.1m          $ cmc #2

xs1 in1 c1 pln plp switch                 $ switch #1
xs2 in2 c2 p2n p2p switch                 $ switch #2
xs3 out c3 pln plp switch                 $ switch #3

* bypass mechanism
mup c1 pln vdd vdd pc1_pm1_du2 w=20u l=2u
mdown c1 plp 0 0 pc1_nm1_du1 w=20u l=2u

* independent sources
vdd vdd 0 5
iin 0 inn pw1(0n 100u 99n 100u 100n -100u 199n -100u 200n 100u) r

* voltage sources
vinn inn c1 0
vol o1 c2 0
vo2 o2 c3 0
vout out 0 2.5

.op 190n
.tran 1n 200n
.print i(vol)
.end

*****
circuit number to circuit name directory
number  circuitname          definition  multiplier
0 main circuit
1 xcth1.                      cth_0.1m    1.00
2 xcth2.                      cth_0.1m    1.00
3 xs1.                        switch       1.00
4 xs2.                        switch       1.00
5 xs3.                        switch       1.00
6 xcth1.xirc.                 irc          1.00
7 xcth1.xibias.               ibs          1.00
8 xcth2.xirc.                 irc          1.00
9 xcth2.xibias.               ibs          1.00

***** operating point information tnom= 25.000 temp= 25.000
*****
***** operating point status    simulation time is 1.900000e-07

node = voltage          node = voltage          node = voltage
+0:c1 = 5.934382e-01    0:c2 = 2.524614e+00    0:c3 = 2.394082e+00
+0:in1 = 2.524614e+00    0:in2 = 2.394082e+00    0:inn = 5.934382e-01
+0:o1 = 2.524614e+00    0:o2 = 2.394082e+00    0:out = 2.500000e+00
+0:pln = 0.             0:plne= 0.             0:plp = 5.000000e+00
+0:plpe= 5.000000e+00    0:p2n = 5.000000e+00    0:p2ne= 5.000000e+00
+0:p2p = 0.             0:p2pe= 0.             0:vdd = 5.000000e+00
+1:d1 = 1.057783e+00    1:d3 = 2.524614e+00    1:g1 = 1.744273e+00

```

```

+1:g3 = 2.271718e+00 1:io = 2.524614e+00 2:d1 = 1.055629e+00
+2:d3 = 2.394082e+00 2:g1 = 2.394082e+00 2:g3 = 2.509777e+00
+2:io = 2.394082e+00 6:d1 = 3.865688e+00 6:d3 = 2.271718e+00
+6:g3 = 2.544107e+00 6:g4 = 3.000000e+00 6:gate= 3.300000e+00
+6:s4 = 1.493356e+00 7:d1 = 4.193644e+00 7:d3 = 2.524614e+00
+7:g3 = 2.592782e+00 7:g4 = 3.000000e+00 7:gate= 3.000000e+00
+7:s4 = 1.494094e+00 8:d1 = 3.866757e+00 8:d3 = 2.509777e+00
+8:g3 = 2.528368e+00 8:g4 = 3.000000e+00 8:gate= 3.300000e+00
+8:s4 = 1.493115e+00 9:d1 = 4.193174e+00 9:d3 = 2.394082e+00
+9:g3 = 2.603299e+00 9:g4 = 3.000000e+00 9:gate= 3.000000e+00
+9:s4 = 1.494253e+00

```

```

nodal capacitance table
node = cap          node = cap          node = cap
+0:c1 = 4.714232e-14 0:c2 = 5.433566e-14 0:c3 = 1.307081e-14
+0:in1 = 1.307081e-14 0:in2 = 5.568331e-14 0:inn = 0.
+0:o1 = 0. 0:o2 = 0. 0:out = 1.307081e-14
+0:pln = 8.797911e-14 0:plne= 1.205583e-14 0:p1p = 8.033732e-14
+0:p1pe= 1.602751e-14 0:p2n = 3.918877e-14 0:p2ne= 8.261420e-15
+0:p2p = 3.723417e-14 0:p2pe= 6.338023e-15 0:vdd = 3.506999e-13
+1:d1 = 2.895702e-13 1:d3 = 3.662455e-14 1:g1 = 9.874538e-14
+1:g3 = 1.590221e-13 1:io = 0. 2:d1 = 2.891111e-13
+2:d3 = 4.526898e-14 2:g1 = 9.831297e-14 2:g3 = 1.591044e-13
+2:io = 0. 6:d1 = 2.848177e-14 6:d3 = 1.916064e-15
+6:g3 = 1.587931e-14 6:g4 = 7.196414e-15 6:gate= 6.531946e-15
+6:s4 = 1.869222e-14 7:d1 = 1.530927e-13 7:d3 = 9.455552e-15
+7:g3 = 6.950175e-14 7:g4 = 7.196413e-15 7:gate= 4.665609e-14
+7:s4 = 1.869231e-14 8:d1 = 2.847801e-14 8:d3 = 1.916064e-15
+8:g3 = 1.587931e-14 8:g4 = 7.196414e-15 8:gate= 6.531946e-15
+8:s4 = 1.869219e-14 9:d1 = 1.531029e-13 9:d3 = 9.455552e-15
+9:g3 = 6.950175e-14 9:g4 = 7.196413e-15 9:gate= 4.664995e-14
+9:s4 = 1.869233e-14

```

total voltage source power dissipation= 8.674306e-03 watts

total current source power dissipation= -5.934382e-05 watts

**** mosfets

```

subckt
element      0:mup      0:mdown      xcth1      xcth1
model        0:pc1_pm1_ 0:pc1_nm1_ 1:m1      1:m2
id          -1.238446e-03 1.138446e-03 9.781839e-05 2.154292e-05
ibs         0. 0. 0. 0.
ibd         4.406562e-14 -5.934382e-15 -1.057783e-14 -2.271719e-14
vgs        -5.000000e+00 5.000000e+00 1.744273e+00 1.057783e+00
vds        -4.406561e+00 5.934382e-01 1.057783e+00 2.271718e+00
vbs         0. 0. 0. 0.
vth        -5.331764e-01 9.508899e-01 9.331427e-01 9.319862e-01
vdsat      -3.103065e+00 2.413697e+00 5.846000e-01 9.110324e-02
beta       2.181342e-04 5.837230e-04 4.114734e-04 2.623843e-03
gam eff    4.768494e-01 1.073972e+00 1.104212e+00 1.062491e+00
gm         3.590319e-04 2.388962e-04 2.297313e-04 2.338926e-04
gds       7.880300e-05 1.576895e-03 2.434883e-06 2.141873e-06
gmb       4.949198e-05 1.355122e-04 1.337150e-04 1.348404e-04
cdtot      4.743372e-15 2.932814e-14 1.165571e-14 2.496883e-14

```

cgtot	2.957350e-14	3.925720e-14	8.331726e-14	9.756327e-14
cstot	2.860302e-14	3.405266e-14	9.687384e-14	8.803911e-14
cbtot	6.353853e-15	1.368191e-14	4.507955e-14	3.700056e-14
cgs	2.421650e-14	2.022961e-14	5.999599e-14	5.999788e-14
cgd	4.743372e-15	1.855013e-14	1.165571e-14	2.496883e-14

subckt	xcth1	xcth1	xcth1	xcth2
element	1:m3	1:ms_sw	1:ms_sw_d	2:m1
model	0:pc1_nm1_	0:pc1_nm1_	0:pc1_nm1_	0:pc1_nm1_
id	9.781840e-05	0.	0.	2.976345e-04
ibs	0.	-2.524615e-14	-1.744274e-14	0.
ibd	-1.466831e-14	-1.744274e-14	-1.744274e-14	-1.055630e-14
vgs	1.213935e+00	-2.524614e+00	3.255726e+00	2.394082e+00
vds	1.466831e+00	-7.803408e-01	0.	1.055629e+00
vbs	0.	-2.524614e+00	-1.744273e+00	0.
vth	9.355824e-01	1.698010e+00	1.772094e+00	9.331458e-01
vdsat	1.995330e-01	0.	1.083438e+00	1.044570e+00
beta	3.270915e-03	3.045259e-04	1.329575e-04	3.955627e-04
gam eff	1.061055e+00	1.069311e+00	1.108779e+00	1.104212e+00
gm	6.173961e-04	0.	0.	3.809397e-04
gds	9.230487e-06	0.	0.	6.412481e-06
gmb	3.511916e-04	0.	0.	2.086094e-04
cdtot	3.328953e-14	3.335013e-15	5.937731e-15	1.165571e-14
cgtot	1.340532e-13	1.205583e-14	8.261420e-15	8.331726e-14
cstot	1.295286e-13	3.335013e-15	6.155374e-15	9.687384e-14
cbtot	5.082256e-14	5.385802e-15	2.132568e-15	4.372365e-14
cgs	8.714646e-14	3.335013e-15	3.898757e-15	6.135189e-14
cgd	3.328953e-14	3.335013e-15	3.898757e-15	1.165571e-14

subckt	xcth2	xcth2	xcth2	xcth2
element	2:m2	2:m3	2:ms_sw	2:ms_sw_d
model	0:pc1_nm1_	0:pc1_nm1_	0:pc1_nm1_	0:pc1_nm1_
id	2.153911e-05	2.976345e-04	2.415754e-12	0.
ibs	0.	0.	-2.394082e-14	-2.394082e-14
ibd	-2.509777e-14	-1.338453e-14	-2.394082e-14	-2.394082e-14
vgs	1.055629e+00	1.454147e+00	2.605917e+00	-2.394082e+00
vds	2.509777e+00	1.338452e+00	1.025173e-08	0.
vbs	0.	0.	-2.394082e+00	-2.394082e+00
vth	9.307729e-01	9.363653e-01	1.904590e+00	1.970539e+00
vdsat	9.039723e-02	3.649046e-01	5.396758e-01	0.
beta	2.664553e-03	3.176994e-03	2.862331e-04	1.487468e-04
gam eff	1.062491e+00	1.061055e+00	1.061031e+00	1.099582e+00
gm	2.356036e-04	1.049883e-03	2.749189e-12	0.
gds	2.073298e-06	2.309359e-05	2.356434e-04	0.
gmb	1.356446e-04	5.821868e-04	7.591837e-13	0.
cdtot	2.496883e-14	3.328953e-14	1.165396e-14	1.670873e-15
cgtot	9.738806e-14	1.341355e-13	1.602751e-14	6.338023e-15
cstot	8.752266e-14	1.297710e-13	1.197945e-14	1.670873e-15
cbtot	3.691564e-14	5.029641e-14	3.313235e-15	2.996276e-15
cgs	5.970776e-14	8.784862e-14	7.781802e-15	1.670873e-15
cgd	2.496883e-14	3.328953e-14	7.781802e-15	1.670873e-15